



AN 796: Cyclone[®] V and Arria[®] V SoC Device Design Guidelines

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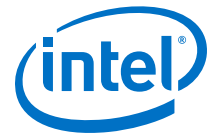


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1. Overview of the Design Guidelines for Cyclone® V SoC FPGAs and Arria® V SoC FPGAs

The purpose of this document is to provide a set of design guidelines and recommendations, as well as a list of factors to consider, for designs that use the Cyclone V SoC and Arria V SoC FPGA devices. This document assists you in the planning and early design phases of the SoC FPGA design, Platform Designer (Standard) sub-system design, board design and software application design.

Note: This application note does not include all the Cyclone V/Arria V Hard Processor System (HPS) device details, features or information on designing the hardware or software system. For more information about the Cyclone V or Arria V HPS features and individual peripherals, refer to the respective Hard Processor System Technical Reference Manual.

Design guidelines for the FPGA portion of your design are provided in the *Arria V and Cyclone V Design Guidelines*.

Related Information

- [Arria V Hard Processor System Technical Reference Manual](#)
- [Cyclone V Hard Processor System Technical Reference Manual](#)
- [Intel MAX 10 FPGA Design Guidelines](#)



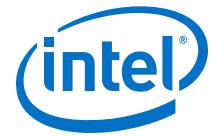
1.1. The SoC FPGA Designer's Checklist

Table 1. The SoC FPGA Designer's Checklist

Step Title	Links	Check (X)
HPS Designer's Checklist for SoC FPGAs		
Start your SoC FPGA Design here	Start your SoC-FPGA design here on page 15	
	Determining your SoC FPGA Topology on page 15	
Design Considerations for Connecting Device I/O to HPS Peripherals and Memory	HPS Pin Assignment Design Considerations on page 17	
	HPS I/O Settings: Constraints and Drive Strengths on page 18	
HPS Clocking and Reset Design Considerations	HPS Clock Planning on page 20	
	Early Pin Planning and I/O Assignment Analysis on page 20	
	Pin Features and Connections for HPS JTAG, Clocks, Reset and PoR on page 20	
	Internal Clocks on page 21	
HPS EMIF Design Considerations	Considerations for Connecting HPS to SDRAM on page 21	
	HPS SDRAM I/O Locations on page 23	
	Integrating the HPS EMIF with the SoC FPGA Device on page 23	
	HPS Memory Debug on page 23	
DMA Considerations	Choosing a DMA Controller on page 25	
	Optimizing DMA Master Bandwidth through HPS Interconnect on page 25	
	Timing Closure for FPGA Accelerators on page 25	
Managing Coherency for FPGA Accelerators	Cache Coherency on page 26	
	Coherency between FPGA Logic and HPS: Accelerator Coherency Port (ACP) on page 26	
	Data Size Impacts ACP Performance on page 26	
	FPGA Access to ACP via AXI or Avalon-MM on page 27	
	Data Alignment for ACP and L2 Cache ECC accesses on page 27	
IP Debug Tools	IP Debug Tools on page 28	
Board Designer's Checklist for SoC FPGAs		
HPS Power Design Considerations	Early System and Board Planning on page 34	
	Early Power Estimation on page 34	
	Design Considerations for HPS and FPGA Power Supplies for SoC FPGA devices on page 35	
	Pin Connection Considerations for Board Designs on page 35	
	Device Power-Up on page 35	
	Power Analysis and Optimization on page 36	
Boundary Scan for HPS	Boundary Scan for HPS on page 37	
Design Guidelines for HPS Interfaces	HPS EMAC PHY Interfaces on page 37	
continued...		



Step Title	Links	Check (X)
	USB Interface Design Guidelines on page 44	
	QSPI Flash Interface Design Guidelines on page 45	
	SD/MMC and eMMC Card Interface Design Guidelines on page 46	
	NAND Flash Interface Design Guidelines on page 47	
	UART Interface Design Guidelines on page 47	
	I2C Interface Design Guidelines on page 48	
	SPI Interface Design Guidelines on page 48	
Embedded Software Designer's Checklist for SoC FPGAs		
Assemble the components of your Software Development Platform	Assembling the Components of Your Software Development Platform on page 50	
	Golden Hardware Reference Design on page 51	
Select an Operating System (OS) for your application	Linux or RTOS on page 53	
	Bare Metal on page 53	
	Using Symmetrical vs. Asymmetrical Multiprocessing (SMP vs. AMP) Modes on page 54	
Assemble your Software Development Platform for Linux	Golden System Reference Design (GSRD) for Linux on page 55	
	GSRD for Linux Development Flow on page 56	
	GSRD for Linux Build Flow on page 57	
	Linux Device Tree Design Considerations on page 58	
Assemble your Software Development Platform for Bare-metal Application	Assembling a Software Development Platform for a Bare-Metal Application on page 59	
Assemble your Software Development Platform for Partner OS/RTOS Application	Assembling your Software Development Platform for a Partner OS or RTOS on page 60	
Choose the Boot Loader Software	Choosing Boot Loader Software on page 60	
Selecting Software Tools for Development, Debug and Trace	Select Software Build Tools on page 62	
	Select Software Debug Tools on page 62	
	Select Software Trace Tools on page 63	
Board Bring Up Considerations	Board Bring Up Considerations on page 29	
Boot and Configuration Design Considerations	Boot Design Considerations on page 29	
	Configuration on page 33	
Flash Device Driver Considerations	Flash Device Driver Design Considerations on page 63	
HPS ECC Design Considerations	HPS ECC Design Considerations on page 64	
HPS SDRAM Considerations	HPS SDRAM Considerations on page 65	



1.2. Overview of HPS Design Guidelines for SoC FPGA design

Table 2. HPS Design Guidelines Overview

Stages of the HPS Design Flow	Guidelines	Links
Hardware and Software Partitioning	Determine your system topology and use it as a starting point for your HPS to FPGA interface design.	Guidelines for Interconnecting the HPS and FPGA on page 10
HPS Pin Multiplexing and I/O Configuration Settings	Plan configuration settings for the HPS system including I/O multiplexing options, interface to FPGA and SDRAM, clocks, peripheral settings	Design Considerations for Connecting Device I/O to HPS Peripherals and Memory on page 16
HPS Clocks and Reset Considerations	HPS clocks and cold and warm reset considerations	HPS Clocking and Reset Design Considerations on page 19
HPS EMIF Considerations	Usage of the HPS EMIF controller and related considerations	HPS EMIF Design Considerations on page 21
FPGA Accelerator Design Considerations	Design considerations to manage coherency between FPGA accelerators and the HPS	DMA Considerations on page 25
Recommended Tools for IP Development	Signal Tap II, BFM, System Console	IP Debug Tools on page 28



1.3. Overview of Board Design Guidelines for SoC FPGA Design

Table 3. Board Design: Design Guidelines Overview

Stages of the Board Design Flow	Guidelines	Links
HPS Power design considerations	Power on board bring up, early power estimation, design considerations for HPS and FPGA power supplies, power analysis and power optimization	HPS Power Design Considerations on page 33
Board design guidelines for HPS interfaces	Includes EMAC, USB, QSPI, SD/MMC, NAND, UART and I ² C	Design Guidelines for HPS Interfaces on page 37



1.4. Overview of Embedded Software Design Guidelines for SoC FPGA Design

Table 4. Embedded Software: Design Guidelines Overview

Stages of the Embedded Software Design Flow	Guidelines	Links
Operating System (OS) considerations	OS considerations to meet your application needs, including real time, software reuse, support and ease of use considerations	Selecting an Operating System for Your Application on page 53
Boot Loader considerations	Boot loader considerations to meet your application needs. including GPL requirements, and features.	Choosing Boot Loader Software on page 60
Boot and Configuration Design Considerations	Boot source, boot clock, boot fuses, configuration flows	Boot and Configuration Design Considerations on page 29
HPS ECC Considerations	ECC for external SDRAM interface, L2 cache data memory, flash memory	HPS ECC Design Considerations on page 64
HPS SDRAM Considerations	Using Preloader to debug HPS SDRAM, Accessing the HPS SDRAM	HPS SDRAM Considerations on page 65

2. Background: Comparison between Cyclone V SoC FPGA and Arria V SoC FPGA HPS Subsystems

While the HPS subsystems in Cyclone V SoC and Arria V SoC are architecturally similar, there are a few differences in features as listed below.

HPS Features	Cyclone V SoC	Arria V SoC
Maximum MPU Frequency	Up to 925 MHz	Up to 1.05 GHz
Controller Area Network (CAN)	Yes	No
Total HPS Dedicated I/O with Loaner capability	Up to 67	94 ⁽¹⁾
Automotive Grade Option	Yes	No
Maximum supported DDR3 Frequency for HPS SDRAM	400 MHz	533 MHz

Related Information

[Differences Among Intel SoC Device Families](#)

2.1. Guidelines for Interconnecting the HPS and FPGA

The memory-mapped connectivity between the HPS and the FPGA fabric is a crucial tool to maximize the performance of your design.

Design guidelines for the FPGA portion of your design are provided in the *Arria V and Cyclone V Design Guidelines*.

Related Information

[Arria V and Cyclone V Design Guidelines](#)

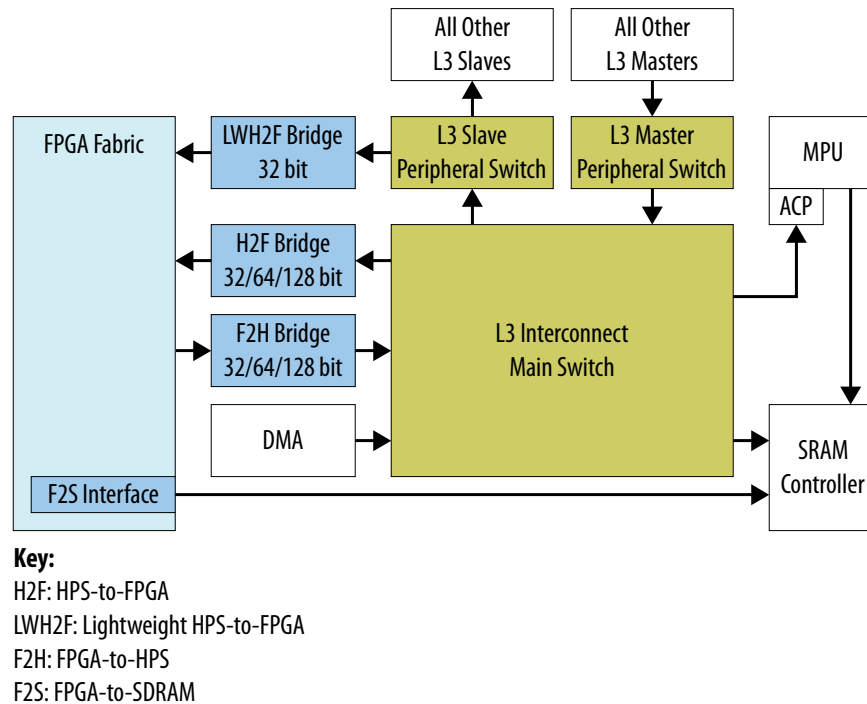
2.1.1. HPS-FPGA Bridges

The HPS has three bridges that use memory-mapped interfaces to the FPGA based on the Arm* Advanced Microcontroller Bus Architecture (AMBA*) Advanced eXtensible Interface (AXI*). Their purpose determines the direction of each bridge.

⁽¹⁾ You can only assign a maximum of 71 HPS I/O as Loaner I/O to the FPGA. For a detailed comparison between the HPS subsystem for Cyclone V SoC and Arria V SoC, refer to *Differences Among Intel SoC Device Families*.



Figure 1. HPS-FPGA Bridges



2.1.1.1. Lightweight HPS-to-FPGA Bridge

GUIDELINE: Use the lightweight HPS-to-FPGA bridge to connect IP that needs to be controlled by the HPS.

The lightweight HPS-to-FPGA bridge allows masters in the HPS to access memory-mapped control slave ports in the FPGA portion of the SoC device. Typically, only the MPU inside the HPS accesses this bridge to perform control and status register accesses to peripherals in the FPGA.

GUIDELINE: Do not use the lightweight HPS-to-FPGA bridge for FPGA memory. Instead use the HPS-to-FPGA bridge for memory.

When the MPU accesses control and status registers within peripherals, these transactions are typically strongly ordered (non-posted). By dedicating the lightweight HPS-to-FPGA bridge to register accesses, the access time is minimized because bursting traffic is routed to the HPS-to-FPGA bridge instead.

The lightweight HPS-to-FPGA bridge has a fixed 32-bit width connection to the FPGA fabric, because most IP cores implement 32-bit control and status registers. However, Platform Designer (Standard) can adapt the transactions to widths other than 32 bits within the FPGA-generated network interconnect.



2.1.1.2. HPS-to-FPGA Bridge

GUIDELINE: Use the HPS-to-FPGA bridge to connect memory hosted by the FPGA to the HPS.

The HPS-to-FPGA bridge allows masters in the HPS such as the microprocessor unit (MPU), DMA, or peripherals with integrated masters to access memory hosted by the FPGA portion of the SoC device. This bridge supports 32, 64, and 128-bit datapaths, allowing the width to be tuned to the largest slave data width in the FPGA fabric connected to the bridge. This bridge is intended to be used by masters performing bursting transfers and should not be used for accessing peripheral registers in the FPGA fabric. Control and status register accesses should be sent to the lightweight HPS-to-FPGA bridge instead.

GUIDELINE: If memory connected to the HPS-to-FPGA bridge is used for HPS boot, ensure that its slave address is set to 0x0 in Platform Designer (Standard).

When the HPS BSEL pins are set to boot from FPGA (BSEL = 1) the processor executes code hosted by the FPGA residing at offset 0x0 from the HPS-to-FPGA bridge. This is the only bridge that can be used for hosting code at boot time.

2.1.1.3. FPGA-to-HPS Bridge

GUIDELINE: Use the FPGA-to-HPS bridge for cacheable accesses to the HPS from masters in the FPGA.

The FPGA-to-HPS bridge allows masters implemented in the FPGA fabric to access memory and peripherals inside the HPS. This bridge supports 32, 64, and 128-bit datapaths so that you can adjust it to be as wide as the widest master implemented in the FPGA.

GUIDELINE: Use the FPGA-to-HPS bridge to access cache-coherent memory, peripherals, or on-chip RAM in the HPS from masters in the FPGA.

Although this bridge has direct connectivity to the SDRAM subsystem, the main intent of the bridge is to provide access to peripherals and on-chip memory, as well as provide cache coherency with connectivity to the MPU accelerator coherency port (ACP).

To access the HPS SDRAM directly without coherency you should connect masters in the FPGA to the FPGA-to-SDRAM ports instead, because they provide much more bandwidth and lower-latency access.

2.1.2. FPGA-to-HPS SDRAM Access

In addition to the FPGA-to-HPS bridge, FPGA logic can also use the FPGA-to-SDRAM interface to access the HPS SDRAM.

GUIDELINE: Use the FPGA-to-SDRAM ports for non-cacheable access to the HPS SDRAM from masters in the FPGA.

The FPGA-to-SDRAM ports allow masters implemented in the FPGA fabric to directly access HPS SDRAM without the transactions flowing through the L3 interconnect.



These interfaces connect only to the HPS SDRAM subsystem so it is recommended to use them in your design if the FPGA needs high-throughput, low-latency access to the HPS SDRAM. The exception to this recommendation is if the FPGA requires cache coherent access to SDRAM.

The FPGA-to-SDRAM interfaces cannot access the MPU ACP slave; so if you require a master implemented in the FPGA to access cache coherent data, ensure that it is connected to the FPGA-to-HPS bridge instead.

The FPGA-to-SDRAM interface has three port types that are used to create the AXI and Avalon-MM interfaces:

- Command ports—issue read as well as write commands, and for receive write acknowledge responses
- 64-bit read data ports—receive data returned from a memory read
- 64-bit write data ports—transmit write data

There is a maximum of six command ports, four 64-bit read data port and four 64-bit write data port. The table below shows the possible port utilization.

Table 5. FPGA-to-HPS SDRAM Port Utilization

Bus Protocol	Command Ports	Read Data Ports	Write Data Ports
32- or 64-bit AXI	2	1	1
128-bit AXI	2	2	2
256-bit AXI	2	4	4
32- or 64-bit Avalon-MM	1	1	1
128-bit Avalon-MM	1	2	2
256-bit Avalon-MM	1	4	4
32- or 64-bit Avalon-MM write-only	1	0	1
128-bit Avalon-MM write-only	1	0	2
256-bit Avalon-MM write-only	1	0	4
32- or 64-bit Avalon-MM read-only	1	1	0
128-bit Avalon-MM read-only	1	2	0
256-bit Avalon-MM read-only	1	4	0

For more information about the FPGA-to-HPS SDRAM interface, refer to the "SDRAM Controller Subsystem" chapter of the *Cyclone V or Arria V SoC Hard Processor System Technical Reference Manual*.

Note: To access the HPS SDRAM via the FPGA-to-SDRAM interface, follow the guidelines in [Access HPS SDRAM via the FPGA-to-SDRAM Interface](#) on page 70.

Related Information

- [SDRAM Controller Subsystem - Cyclone V Hard Processor System Technical Reference Manual](#)
- [SDRAM Controller Subsystem - Arria V Hard Processor System Technical Reference Manual](#)



2.1.3. Connecting Soft Logic to HPS Component

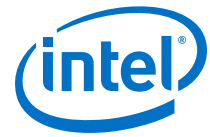
Designers can connect soft logic components to the HPS using the Cyclone V/Arria V HPS component in Platform Designer (Standard).

Note: Refer to the "Introduction to the HPS Component" and "Instantiating the HPS Component" chapters of the appropriate *Hard Processor System Technical Reference Manual* to understand the interface and available options. To connect a FPGA soft IP component to the HPS, Platform Designer (Standard) provides the component editor tool. For more information, refer to the "[Creating Platform Designer \(Standard\) Components](#)" chapter of the *Intel® Quartus® Prime Standard Edition Handbook*, Volume 1: *Design and Synthesis*.

Note: When designing and configuring high bandwidth DMA masters and related buffering in the FPGA core, refer to the [DMA Considerations](#) on page 25 section of this document. The principles covered in that section apply to all high bandwidth DMA masters (for example Platform Designer (Standard) DMA Controller components, integrated DMA controllers in custom peripherals) and related buffering in the FPGA core that access HPS resources (for example HPS SDRAM) through the FPGA-to-SDRAM and FPGA-to-HPS bridge ports, not just tightly coupled Arm CPU accelerators.

Related Information

- [Introduction to the HPS Component - Cyclone V Hard Processor System Technical Reference Manual](#)
- [Instantiating the HPS Component - Cyclone V Hard Processor System Technical Reference Manual](#)
- [Introduction to the HPS Component - Arria V Hard Processor System Technical Reference Manual](#)
- [Instantiating the HPS Component - Arria V Hard Processor System Technical Reference Manual](#)



3. Design Guidelines for HPS portion of SoC FPGAs

3.1. Start your SoC-FPGA design here

3.1.1. Recommended Starting Point for HPS-to-FPGA Interface Design

Depending on your topology, you can choose one of the two hardware reference designs as a starting point for your hardware design.

GUIDELINE: Use the Golden System Reference Design (GSRD) as a starting point for a loosely coupled system.

The Golden Hardware Reference Design (GHRD) has the optimum default settings and timing that you can use as a basis for your "getting started" system. After initial evaluation, you can move on to the Cyclone V HPS-to-FPGA Bridge Design Example reference design to compare performance among the various FPGA-HPS interfaces.

Refer to "Golden Hardware Reference Design" for more information.

GUIDELINE: Use the Cyclone V HPS-to-FPGA Bridge Design Example reference design to determine your optimum burst length and data-width for accesses between FPGA logic and HPS.

The [Cyclone V FPGA-to-HPS bridge design example](#) contains modular SGDMAs in the FPGA logic that allow you to program the burst length for data accesses from the FPGA logic to the HPS.

Related Information

[Golden Hardware Reference Design](#) on page 51

3.1.2. Determining your SoC FPGA Topology

To determine which system topology best suits your application, you must first determine how to partition your application into hardware and software.

GUIDELINE: Profile your software to identify functions for hardware acceleration.

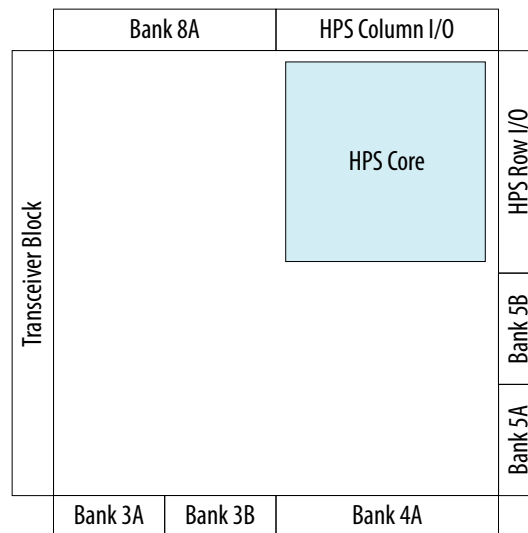
Use any good profiling tool (such as DS-5 streamline profiler) to identify functions that are good candidates for hardware acceleration, and isolate functions that are best implemented in software.

3.2. Design Considerations for Connecting Device I/O to HPS Peripherals and Memory

One of the most important considerations when configuring the HPS is to understand how the I/O is organized in the Cyclone V/Arria V SoC devices. The HPS I/O is physically divided into:

- HPS Column I/O: Contains the HPS Dedicated Function Pins and HPS Dedicated I/O with loaner capability
- HPS Row I/O: Contains the HPS External Memory Interface (EMIF) I/O and HPS General Purpose Input (GPI) pins

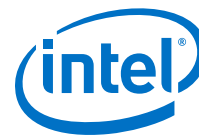
Figure 2. Example layout for HPS Column I/O and HPS Row I/O in Cyclone V SX and ST device



Note: For more information regarding the I/O pin layout, refer to the appropriate "I/O Features" chapter in the *Cyclone V* or *Arria V Device Handbook*, Volume 1: *Device Interfaces and Integration*.

Table 6. HPS I/O Pin Type Summary

Pin Type	Purpose
HPS Dedicated Function Pins	Each I/O has only one function and cannot be used for other purposes.
HPS Dedicated I/O with loaner capability	These I/Os are primarily used by the HPS, but can be used on an individual basis by the FPGA if the HPS is not using them.
HPS External Memory Interface (EMIF) I/O	These I/Os are used for connecting to the HPS external memory interface (EMIF). Refer to the "External Memory Interface in Cyclone V Devices" or "External Memory Interface in Arria V Devices" chapter in the respective device handbook for more information regarding the layout of these I/O pins.
HPS General Purpose Input (GPI) Pins	These pins are also known as HLGPI pins. These input-only pins are located in the same bank as the HPS EMIF I/O. Note that the smallest Cyclone V SoC package U19 (484 pins) does not have any HPS GPI pins.
FPGA I/O	These are general purpose I/O that can be used for FPGA logic and FPGA External Memory Interfaces.



The table below summarizes the characteristics of each I/O type.

Table 7. I/O Types

	HPS Dedicated Function Pins	HPS Dedicated I/O with loaner capability	HPS External Memory Interface	HPS General Purpose Input	FPGA I/O
Number of Available I/O	11	Up to 67 (Cyclone V SoC) and 94 (Arria V SoC)	Up to 86	14 (except for Cyclone V SoC U19 package)	Up to 288 (Cyclone V SoC) and Up to 592 (Arria V SoC)
Voltages Supported	3.3V, 3.0V, 2.5V, 1.8V, 1.5V	3.3V, 3.0V, 2.5V, 1.8V, 1.5V	LVDS I/O for DDR3, DDR2 and LPDDR2 protocols	Same as the I/O bank voltage used for HPS EMIF	3.3V, 3.0V, 2.5V, 1.8V, 1.5V, 1.2V
Purpose	Clock, Reset, HPS JTAG	Boot source, High speed HPS peripherals	Connect to SDRAM	General Purpose Input	General Purpose I/O
Timing Constraints	Fixed	Fixed	Fixed for legal combinations	Fixed	User defined
Recommended Peripherals	JTAG	QSPI, NANDx8, eMMC, SD/MMC, UART, USB, EMAC	DDR3, DDR2 and LPDDR2 SDRAM	GPI	Slow speed peripherals (I ² C, SPI, EMAC-MII)

Note: You can access the timing information to perform off-chip analysis by reviewing the HPS timing in the [Cyclone V Device Datasheet](#) or [Arria V Device Datasheet](#).

Related Information

- [I/O Features in Cyclone V Devices](#)
Chapter in the *Cyclone V Device Handbook*, Volume 1: *Device Interfaces and Integration*
- [I/O Features in Arria V Devices](#)
Chapter in the *Arria V Device Handbook*, Volume 1: *Device Interfaces and Integration*

3.2.1. HPS Pin Assignment Design Considerations

Because the HPS contains more peripherals than can all be connected to the HPS Dedicated I/O, the HPS component in Platform Designer (Standard) offers pin multiplexing settings as well as the option to route most of the peripherals into the FPGA fabric. Any unused pins for the HPS Dedicated I/O with loaner capability meanwhile can be used as general purpose I/O by the FPGA.

Note that a HPS I/O Bank can only support a single supply of either 1.2V, 1.35V, 1.5V, 1.8V, 2.5V, 3.0V, or 3.3V power supply, depending on the I/O standard required by the specified bank. 1.35V is supported for HPS Row I/O bank only.

GUIDELINE: Ensure that you route USB, EMAC and Flash interfaces to HPS Dedicated I/O first, starting with USB.

It is recommended that you start by routing high speed interfaces such as USB, Ethernet, and flash to the HPS Dedicated I/O first. USB must be routed to HPS Dedicated I/O because it is not available to the FPGA fabric. The flash boot source must also be routed to the HPS dedicated I/O (and not any FPGA I/O) since these are the only I/Os that are functional before the FPGA I/Os have been configured.

Note: For Cyclone V SoC U19 package (484 pin count) only one USB controller (instead of two) is usable due to reduced number of available HPS I/O. For more information, refer to [Why can't I map USB0 to HPS IO in my Cyclone V SoC U19 package \(484 pin count\)?](#) in the Knowledge Base.

GUIDELINE: Enable the HPS GPI pins in the Platform Designer (Standard) HPS Component if needed

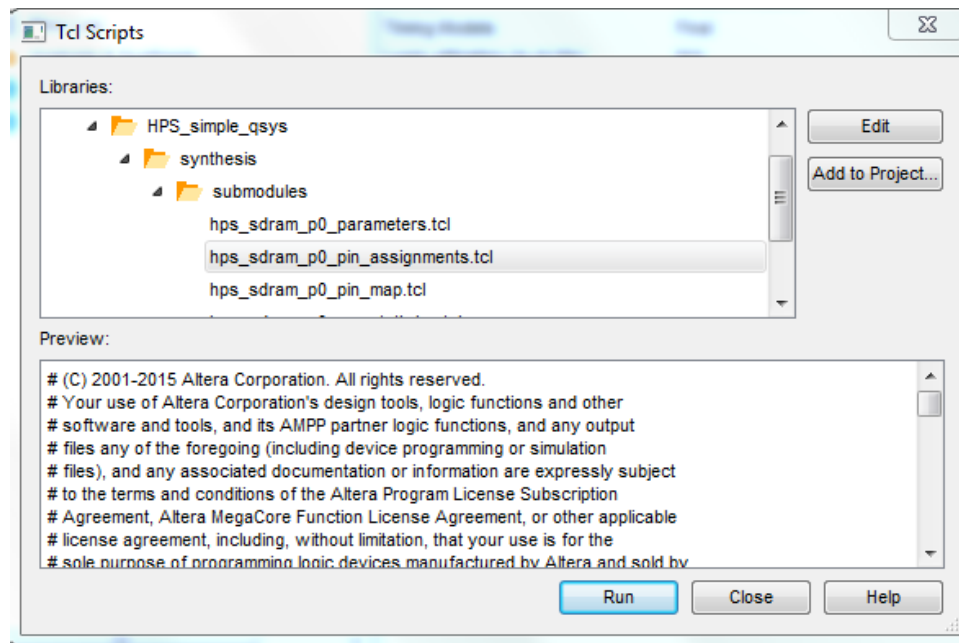
By default, the HPS GPI interface is not enabled in Platform Designer (Standard). To enable this interface, you must select the checkbox "Enable HLGPI interface" in the Platform Designer (Standard) HPS Component for Cyclone V/Arria V. These pins are then exposed as part of the Platform Designer (Standard) HPS Component Conduit Interface and can be individually assigned at the top level of the design.

3.2.2. HPS I/O Settings: Constraints and Drive Strengths

GUIDELINE: Ensure that you have I/O settings for the HPS Dedicated I/O (drive strength, I/O standard, weak pull-up enable, etc.)

The HPS pin location assignments are managed automatically when you generate the Platform Designer (Standard) system containing the HPS. As for the HPS SDRAM, the I/O standard and termination settings are done once you run the "hps_sdram_p0_pin_assignments.tcl" script that is created once the Platform Designer (Standard) HPS Component has been generated.

Note: You can locate the script "hps_sdram_p0_pin_assignments.tcl" in the following directory once the Platform Designer (Standard) HPS Component has been generated: `<Quartus project directory>\<Platform Designer (Standard) file name>\synthesis\submodule`. Shown below is an example of selecting the script in Intel Quartus Prime.



The only HPS I/O constraints you must manage are for HPS Dedicated Function Pins and HPS Dedicated I/O. Constraints such as drive strength, I/O standards, and weak pull-up enables are added to the Intel Quartus Prime project just like FPGA constraints and are applied to the HPS at boot time when the second stage bootloader configures the I/O. For FPGA I/O, the I/O constraints are applied to the FPGA configuration file.

Note: During power up, the HPS Dedicated I/O required for boot flash devices are configured by the Boot ROM, depending on the BSEL values.

3.3. HPS Clocking and Reset Design Considerations

The main clock and resets for the HPS subsystem are HPS_CLK1, HPS_CLK2, HPS_nPOR, HPS_nRST and HPS_PORSEL. HPS_CLK1 sources the Main PLL that generates the clocks for the MPU, L3/L4 sub-systems, debug sub-system and the Flash controllers. It can also be programmed to drive the Peripheral and SDRAM PLLs. HPS_CLK2 meanwhile can be used as an alternative clock source to the Peripheral and the SDRAM PLLs.

HPS_nPOR provides a cold reset input, and HPS_nRST provides a bidirectional warm reset resource. As for the HPS_PORSEL, it is an input pin that can be used to select either a standard POR delay or a fast POR delay for the HPS block.

Note: Refer to the [Cyclone V Device Family Pin Connection Guidelines](#) or [Arria V GT, GX, ST, and SX Device Family Pin Connection Guidelines](#) for more information on connecting the HPS clock and reset pins.

3.3.1. HPS Clock Planning

GUIDELINE: Verify MPU and peripheral clocking using Platform Designer (Standard)

Use Platform Designer (Standard) to initially define your HPS component configuration. Set the HPS input clocks, and peripheral source clocks and frequencies. Note any Platform Designer (Standard) warning or error messages. You can address them by modifying clock settings. In some cases you might determine that a particular warning condition does not impact your application.

3.3.2. Early Pin Planning and I/O Assignment Analysis

GUIDELINE: Choose an I/O voltage level for the HPS Dedicated Function I/O

HPS_CLK1, HPS_CLK2, HPS_nPOR and HPS_nRST are powered by VCCRSTCLK_HPS. These HPS Dedicated Function Pins are LVCMOS/LVTTL at either 3.3V, 3.0V, 2.5V or 1.8V. The I/O signaling voltage for these pins are determined by the supply level applied to VCCRSTCLK_HPS.

Note: HPS_PORSEL can be connected to either VCCRSTCLK_HPS (for fast HPS POR delay) or GND (for standard HPS POR delay).

Note: VCCRSTCLK_HPS can share the same power and regulator with VCCIO_HPS and VCCPD_HPS if they share the same voltage requirement. The functionality of powering down the FPGA fabric, while keeping the HPS running, is not needed.

3.3.3. Pin Features and Connections for HPS JTAG, Clocks, Reset and PoR

GUIDELINE: With the HPS in use (powered), supply a free running clock on HPS_CLK1 for SoC device HPS JTAG access.

Access to the HPS JTAG requires an active clock source driving HPS_CLK1.

GUIDELINE: When daisy chaining the FPGA and HPS JTAG for a single device, ensure that the HPS JTAG is first device in the chain (located before the FPGA JTAG).

Placing the HPS JTAG before the FPGA JTAG allows the ARM DS-5 debugger to initiate warm reset to the HPS. However, in case of cold reset the entire JTAG chain is broken until the cold reset completes, as discussed in the next section.

GUIDELINE: Consider board design to isolate HPS JTAG interface

The HPS Test Access Port (TAP) controller is reset on a cold reset. If the HPS JTAG and FPGA JTAG are daisy-chained together, the entire JTAG chain is broken until the cold reset completes. If access to the JTAG chain is required during HPS cold reset, design the board to allow HPS JTAG to be bypassed.

GUIDELINE: HPS_nRST is an open-drain, bidirectional dedicated warm reset I/O.

HPS_nRST is an active low, open-drain-type, bidirectional I/O. Externally asserting a logic low to the HPS_nRST pin initiates a warm reset of the HPS subsystem. HPS warm and cold reset can also be asserted from internal sources such as software-initiated



resets and reset requests from the FPGA fabric. When the HPS is internally placed in a warm reset state, the HPS component becomes a reset source and drives the HPS_nRST pin low, resetting any connected board-level components.

GUIDELINE: Observe the minimum assertion time specifications of HPS_nPOR and HPS_nRST.

Reset signals on the HPS_nPOR and HPS_nRST pins must be asserted for a minimum number of HPS_CLK1 cycles as specified in the HPS section of the [Cyclone V Device Datasheet](#) or [Arria V Device Datasheet](#).

3.3.4. Internal Clocks

GUIDELINE: Avoid cascading PLLs between the HPS and FPGA

Cascading PLLs between the FPGA and HPS has not been characterized. Unless you perform the jitter analysis, do not chain the FPGA and HPS PLLs together as a stable clock coming out of the last PLL in the FPGA cannot be guaranteed. Output clocks from the HPS are not intended to be fed into PLLs in the FPGA.

3.4. HPS EMIF Design Considerations

A critical component of the HPS subsystem is the external SDRAM memory. For Cyclone V and Arria V SoC device, the HPS has a dedicated SDRAM Subsystem that interfaces with the HPS External Memory Interface I/O.

Review the following guidelines to properly design the interface between the memory and the HPS. These guidelines are essential to successfully connecting external SDRAM to the HPS.

The [External Memory Interface Handbook, Volume 3: Reference Material](#) includes the functional description of the HPS memory controller. The supported interface options are listed for DDR3, DDR2 and LPDDR2.

3.4.1. Considerations for Connecting HPS to SDRAM

GUIDELINE: Ensure that the HPS memory controller Data Mask (DM) pins are enabled

In the HPS Component in Platform Designer (Standard), ensure that the checkbox to enable the data mask pins is enabled. If this control is not enabled, data corruption occurs any time a master accesses data in SDRAM that is smaller than the native word size of the memory.

Figure 3. Setting the Enable DM Pins Option in HPS Component

The screenshot shows the 'Arria V/Cyclone V Hard Processor System' configuration window. The 'SDRAM' tab is selected, and the 'Memory Parameters' sub-tab is active. The 'SDRAM Protocol' is set to 'DDR3'. The 'Memory vendor' is 'JEDEC', 'Memory format' is 'Discrete Device', and 'Memory device speed grade' is '800.0 MHz'. Other parameters include 'Total interface width: 40', 'Number of DQS groups: 5', 'Number of chip select/depth expansion: 1', 'Number of clocks: 1', 'Row address width: 15', 'Column address width: 10', and 'Bank-address width: 3'. The 'Enable DM pins' checkbox is checked, and the 'DQS# Enable' checkbox is also checked.

Determine your SDRAM Memory type and bit width. Cyclone V and Arria V SoC devices offer DDR3, DDR2 and LPDDR2 SDRAM support for the HPS.

GUIDELINE: Ensure that you choose only DDR3, DDR2, or LPDDR2 components or modules in configurations supported by the Cyclone V or Arria V HPS EMIF for your specific device/package combination.

The External Memory Interface Spec Estimator, available on the [External Memory Interface](#) page, is a parametric tool that allows you to compare supported external memory interface types, configurations and maximum performance characteristics in Intel FPGA and SoC devices.

First, filter the "Family" to select only Cyclone V /Arria V SoC device. Then, follow on by using the filter on "Interface Type" to choose only "HPS Hard Controller"

GUIDELINE: Ensure that in the HPS Component, the Memory Clock Frequency is supported by the device speed grade.

To obtain the maximum supported memory clock frequency for the device speed grade, refer to the External Memory Interface Spec Estimator, available on the [External Memory Interface](#) page.



3.4.2. HPS SDRAM I/O Locations

The Cyclone V and Arria V SoC HPS External Memory Interface I/O locations are fixed, depending on the type of memory used. You can refer to the device Pin Out files, under the "HMC Pin Assignment for DDR3/DDR2" and "HMC Pin Assignment for LPDDR2" for exact I/O pins used by the respective memory interface pins.

Note: Unused HPS External Memory Interface I/O Pins cannot be assigned to HPS Peripherals, or used by the FPGA as Loaner IO.

Note: The smallest Cyclone V SoC package U19 (484 pin count) has narrower HPS SDRAM width (32-bit) compared to larger packages (40-bit). Refer to the ["External Memory Interfaces in Cyclone V Devices"](#) chapter in *Cyclone V Device Handbook Volume 1: Device Interfaces and Integration* for more information.

Related Information

Documentation: [Pin-Out Files for Intel FPGA Devices](#)

3.4.3. Integrating the HPS EMIF with the SoC FPGA Device

Consider the following when integrating the Cyclone V or Arria V SoC HPS EMIF with the rest of the SoC system design.

GUIDELINE: Follow the guidelines for optimizing bandwidth for all masters accessing the HPS SDRAM

Accesses to SDRAM connected to the HPS EMIF go through the L3 Interconnect (except for FPGA-to-SDRAM bridge). When designing and configuring high bandwidth DMA masters and related buffering in the FPGA core, refer to [DMA Considerations](#) on page 25. The principles covered in that section apply to all high bandwidth DMA masters (for example DMA controller components, integrated DMA controllers in custom peripherals) and related buffering in the FPGA core that access HPS resources (for example HPS SDRAM) through the FPGA-to-SDRAM and FPGA-to-HPS bridge ports, not just tightly-coupled HPS hardware accelerators.

3.4.4. HPS Memory Debug

The Cyclone V / Arria V HPS EMIF do not support the external memory interface toolkit. To debug the HPS EMIF, you can change the settings inside the preloader software to enable Runtime Calibration Report and Debug Level info. In addition, you can use the preloader software to check the status of HPS SDRAM PLL.

Refer to [Using the Preloader To Debug the HPS SDRAM](#) on page 65 for more information.

3.4.5. HPS Address Mirroring

The Cyclone V and Arria V HPS EMIF support address mirroring. This feature can be turned on under the **Memory Initialization Options** sub-window in the **Memory Parameters** tab under the **Interface Type** sub-window of the **DDR3 SDRAM Controller with UniPHY** GUI. For example, for four chip selects, enter 1011 to mirror the address on chip select #3, #1, and #0.

For more information about address mirroring, refer to *External Memory Interface Handbook, Volume 1: Introduction and Specifications*.

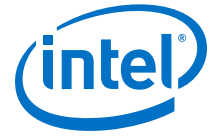
Figure 4. HPS Address Mirroring

The screenshot shows the 'DDR3 SDRAM Controller with UniPHY' configuration window. The 'Memory Parameters' tab is selected. The 'Memory Initialization Options' section is highlighted with a red box, showing the 'Mirror Addressing: 1 per chip select' option set to 0.

Parameter	Value
Memory vendor	JEDEC
Memory format	Discrete Device
Memory device speed grade	4000
Total interface width	8
DQ/DQS group size	8
Number of DQS groups	1
Number of chip selects	1
Number of clocks	1
Row address width	12
Column address width	8
Bank address width	3
Enable DV DRs	<input checked="" type="checkbox"/>
Memory Initialization Options	
Mirror Addressing: 1 per chip select	0

Related Information

[External Memory Interface Handbook, Volume 1: Introduction and Specifications](#)



3.5. DMA Considerations

3.5.1. Choosing a DMA Controller

Choose the DMA implementation best suited to your design

When DMA is required to improve system performance, you have the option to use the DMA integrated into the HPS or a soft DMA module in the FPGA. When making the choice of which option to use, you should consider the following:

- HPS DMA: primarily used to move data to and from other slow-speed HPS modules, such as SPI and I²C, as well as to do memcpy functions to and from HPS memories.
- Soft DMAs: primarily used to move data to and from peripherals in the FPGA.

3.5.2. Optimizing DMA Master Bandwidth through HPS Interconnect

FPGA DMA masters have access to HPS resources through the FPGA-to-HPS Bridge and FPGA-to-SDRAM Interface, configurable in the HPS Platform Designer (Standard) Component. The HPS SDRAM controller multi-port-front end (MPFE) provides arbitration for these resources and enforce Quality of Service (QoS) settings. When planning for and designing DMA masters and related buffering that access resources through the HPS interconnect, study the architecture of the HPS interconnect and consider the following guidance and resources available for optimizing bandwidth through the interconnect.

GUIDELINE: Utilize the Cyclone V FPGA-to-HPS Bridge Design Example to tune for performance

The [Cyclone V FPGA-to-HPS Bridge Design Example](#) is a useful platform for modeling specific data traffic access patterns between the FPGA and HPS resources.

The example design includes a utility that can select the datapaths between endpoints, select transaction characteristics (for example, burst lengths), and report transfer bandwidth. This utility runs on the ARM Cortex* A-9 processor in the HPS.

3.5.3. Timing Closure for FPGA Accelerators

The HPS bridges and FPGA-to-SDRAM interfaces exposed to the FPGA are synchronous and clock crossing is performed within the interface itself. As a result, you only need to ensure that both the FPGA-facing logic and your user design close timing in Timing Analyzer. Interrupts are considered asynchronous by the HPS, and as a result the HPS logic resynchronizes them to the internal HPS clock domain so there is no need to close timing for them.

Conduits carry signals that do not fit into any standard interface supported by Platform Designer (Standard). Examples of these are HPS peripheral external interfaces routed into the FPGA fabric or the HPS DMA peripheral request interfaces.

3.6. Managing Coherency for FPGA Accelerators

Data shared between the HPS and the FPGA logic can be modified at any time, by either the HPS or the FPGA. Many applications require data coherency, which means that changes are propagated throughout the system, so that every master accesses the most up-to-date data value.

When you design for data coherency, first you must determine which data transfers need to be coherent. By default all access between the FPGA and HPS are assumed to be non-coherent unless coherency is explicitly managed by software or using coherent hardware features of the HPS (SCU and ACP).

To determine if peripherals in the FPGA need coherent access to HPS memory, answer the follow questions:

- Does the MPU need to access data generated by my FPGA peripheral?
- Does the FPGA peripheral need to access data generated by the MPU?

If the answer to either question is "Yes", the data must be coherent. You can use the ACP to keep the FPGA coherent with cacheable data in the HPS.

3.6.1. Cache Coherency

There are several mechanisms via which coherency are maintained through the system:

The HPS maintains cache coherency at a level 1 memory subsystem level within the MPU subsystem. The snoop control unit (SCU) built into the MPU subsystem maintains cache coherency between the two L1 data caches using the modified-exclusive-shared-invalid (MESI) coherency protocol.

3.6.2. Coherency between FPGA Logic and HPS: Accelerator Coherency Port (ACP)

The accelerator coherency port (ACP) of the SCU provides a means for other masters in the system, including logic implemented in the FPGA fabric, to perform cache coherent accesses. Accesses to the ACP are only unidirectional in terms of cache coherency meaning at the time of the access the data is up to date, but the SCU is not responsible for maintaining coherency of that data over time. For example, if a master in the FPGA reads data from the ACP and then a processor updates that same data in memory, then the FPGA no longer contains the most up to date copy of the data.

3.6.3. Data Size Impacts ACP Performance

Performance explorations of accelerators using ACP show that as size of packets transferred by AXI master via the ACP port increases the accelerator performance increases but only up to a point. After that point, it is no longer possible to cache the entire data packet, and the accelerator suffers performance degradation.



GUIDELINE: Use ACP for managing coherency for small data size accesses, manage coherency for large data in software.

3.6.4. Avoiding ACP Dependency Lockup

Certain coherent access scenarios can create deadlock through the ACP and the CPU. However, you can avoid this type of deadlock with a simple access strategy.

In the following example, the CPU creates deadlock by initiating an access to the HPS through the FPGA fabric:

1. The CPU initiates a device memory access to the FPGA fabric. The CPU pipeline must stall until this type of access is complete.
2. Before the FPGA fabric state machine can respond to the device memory access, it must access the HPS coherently. It initiates a coherent access, which requires the ACP.
3. The ACP must perform a cache maintenance operation before it can complete the access. However, the CPU's pipeline stall prevents it from performing the cache maintenance operation. The system deadlocks.

You can implement the desired access without deadlock, by breaking it into smaller pieces. For example, you can initiate the operation with one access, then determine the operation status with a second access.

3.6.5. FPGA Access to ACP via AXI or Avalon-MM

The AXI protocol allows masters to issue cacheable accesses whereas the Avalon-MM protocol does not support this feature. For an FPGA master to perform a cacheable access, the master must adhere to the AXI protocol and be able to perform cacheable accesses, with `ARCACHE[1]` or `AWCACHE[1]` set to 1 and `ARUSER[0]` or `AWUSER[0]` set to 1.

3.6.6. Data Alignment for ACP and L2 Cache ECC accesses

The L2 cache performs error detection and correction in groups of 64 bits without the use of byte enables.

GUIDELINE: Accesses to the ACP must be 64-bit aligned, full 64-bit accesses, and no byte lanes can disabled on write.

The main L3 switch and the ACP port are both 64 bits wide, so it is only necessary to provide 64-bit aligned cache coherent accesses that are 64 bits wide after resizing.

Data resizing can occur in the L3 interconnect between requesting master and the ACP. As a result, a 32-bit access can be compatible with the L2 cache ECC logic if the access is aligned to 8-byte boundaries and the master performs bursts of size 2, 4, 8, or 16. Data resizing can also occur within the FPGA-to-HPS bridge.

GUIDELINE: The simplest way to ensure that accesses from the FPGA meets the L2 cache ECC requirements is to implement 64-bit masters in the FPGA fabric and configure the FPGA-to-HPS bridge to expose a 64-bit slave port. This ensures that no resizing of AXI transactions is necessary. Full 64-bit accesses have to be made by the logic in the FPGA as well.

3.7. IP Debug Tools

The Intel Quartus Prime Design Software includes many IP and system-level debug tools used in FPGA hardware designs.

The following tools are commonly used for system and IP debug in embedded systems:

- Signal Tap - On-chip logic analyzer constructed from FPGA resources
- Bus functional models
 - Avalon-MM v2 protocol
 - AXI v3 protocol
- System console - Services-based API for controlling soft logic and moving data to/from the FPGA

Each debug tool is introduced at different stages of the hardware design. In a typical hardware design flow, the developer follows these high-level verification steps:

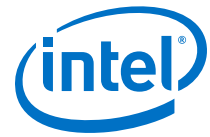
1. IP Creation in RTL
2. Testbench and BFM verification of the IP
3. In silicon testing of the IP using system console to drive stimuli into memory-mapped or streaming interface
4. In silicon testing of the IP using low level software run on the processor in the HPS

In the case of Signal Tap and system console, if both use the FPGA JTAG interface to communicate data then they can be used simultaneously. For example, you may instrument a trigger condition in Signal Tap and cause the trigger condition to occur via the JTAG-to-Avalon bridge IP controlled by System console. These tools are also capable of being used simultaneously with the HPS tools that communicate over JTAG.

There are two JTAG interfaces on the Cyclone V/Arria V SoC device. The first interface is connected to the FPGA side of the device, while the second interface is connected to the HPS debug access port (DAP).

Related Information

- ["Design Debugging Using In-System Sources and Probes" chapter of the *Intel Quartus Prime Standard Edition Handbook Volume 3: Verification*](#)
Description of Signal Tap
- [Avalon-MM v2 protocol](#)
- [AXI v3 protocol](#)
- ["System Debugging Tools Overview" chapter of the *Intel Quartus Prime Standard Edition Handbook Volume 3: Verification*](#)
Description of System Console



4. Board Design Guidelines for SoC FPGAs

4.1. Board Bring Up Considerations

This section describes the considerations that are useful for board bring up.

4.1.1. Reserved BSEL Setting

During initial stages of bring-up, if a JTAG connection cannot be established to the target, it may be beneficial to set BSEL to 0x0 "Reserved" setting to prevent the BootROM from trying to boot from a specific boot source. Then a test program could be downloaded and ran with a debugger.

4.2. Boot and Configuration Design Considerations

4.2.1. Boot Design Considerations

4.2.1.1. Boot Source

GUIDELINE: Determine which boot source is to be supported.

The HPS side of the Cyclone V SoC / Arria V SoC can be booted from a variety of sources, as selected by the BSEL pins:

- SD/MMC Flash
- QSPI Flash
- NAND Flash
- FPGA Fabric

Each possible boot source has its own strengths:

- SD cards are cheap, universally available, and have large storage capacities. Industrial versions available, with improved reliability. They are managed NAND flash, so wear leveling and bad block management are performed internally.
- eMMC devices have smaller packages, are available in large capacities, and can be more reliable than SD. They are not removable, with can be a plus, allowing a more rugged operation.
- QSPI devices are very reliable, typically with a minimum 100,000 cycles of erase cycles per sector. However, they have less capacity than the other options. They are typically used as a boot source, but not as an application filesystem.
- NAND devices are available in large sizes, but they are unmanaged NAND, which means that techniques such as wear leveling and bad block management need to be implemented in software.
- FPGA boot allows HPS to boot without the need of an external Flash device. The FPGA boot memory can be synthesized out of FPGA resources (typically pre-initialized embedded memory blocks) or can be memory connected to the FPGA such as an external SRAM or SDRAM. To boot from FPGA, the FPGA must be configured using a traditional configuration mechanism.

4.2.1.2. Select Desired Flash Device

GUIDELINE: Select the boot flash device.

When choosing a flash device to incorporate with SoC FPGA devices, it is important to consider the following:

- **Is the flash device compatible with the HPS boot ROM ?**: The HPS can only boot from flash devices supported in the boot ROM.
- **Is the device verified to work and supported by software like Preloader, U-Boot and Linux ?**: For supported devices, Intel provides the Preloader, U-Boot and Linux software. For other devices, this software must be developed by the user.
- **Is the flash device supported by the HPS Flash Programmer?**: The HPS Flash Programmer enables writing to flash using a JTAG connection, primarily to program the initial pre-loader/bootloader image. If the device is not supported by the HPS Programmer, other flash programming methods may be used, such as using the HPS to program flash. For example, the flash programming capabilities of U-Boot can be used.

Refer to [Supported Flash Devices for Cyclone V SoC and Arria V SoC](#) for more information.

4.2.1.3. BSEL Options

GUIDELINE: Configure the BSEL pins for the selected boot source.

The boot source is selected by means of BSEL pins.

It may be beneficial to change the boot source for debugging purposes, even if the board does not have available another boot source. For example, on a board booting from QSPI it may be beneficial to select the reserved boot so that BootROM would not do anything. Or select boot from FPGA and put a test image in the FPGA fabric.

If the system allows it (space constraints etc.) plan to provide either switches or at least resistors to be able to change BSEL as needed.



4.2.1.4. Boot Clock

GUIDELINE: Determine boot clock source.

The boot clock influences the boot duration. Consider your system boot speed requirement as the primary factor in choosing the boot clock. The system boot time requirement depends on how fast the FPGA needs to be configured for an appropriate response time, and how quickly the HPS software must be booted. The HPS software boot speed is influenced by the following factors:

- Value of external clock to the HPS (i.e. OSC1 clock)
- Boot flash source interface operation frequency

Boot clock configurations are selected with the CSEL pins. Available combinations are described in the appropriate *Hard Processor System Technical Reference Manual*.

Note: CSEL pins are not used when booting from FPGA fabric.

Related Information

- [Cyclone V Hard Processor System Technical Reference Manual](#)
- [Arria V Hard Processor System Technical Reference Manual](#)

4.2.1.5. CSEL Options

GUIDELINE: Provide a method to configure CSEL options.

For debugging purposes, it may be beneficial to allow setting of various CSEL values even if the end product requires just one CSEL setting. If possible, design the board in such a way that the CSEL configuration can be varied even if a single value can be used eventually. This configurability may be useful for debugging and could be done by resistors, jumpers or switches.

4.2.1.6. Selecting NAND Flash Devices

GUIDELINE: Select a NAND flash that is ONFI 1.0 compliant.

When booting from NAND, ensure that the selected device is ONFI 1.0 compliant.

The NAND device used for booting must also have a $\times 8$ interface, and only a single pair of $\text{ce}\#$ and $\text{rb}\#$ pins.

Although some non-ONFI 1.0 compliant devices are compatible with the BootROM, the HPS Flash Programmer only supports ONFI compliant devices.

4.2.1.7. Determine Flash Programming Method

GUIDELINE: Ensure that the board is configured properly to support flash programming.

The HPS Flash Programmer is a tool provided with SoC EDS that can be used to program QSPI and NAND flash devices on Cyclone V / Arria V SoC boards. The tool is intended to write relatively small amounts of data (for example the preloader) since it works over JTAG and has a limited speed.

If the HPS Flash Programmer tool is to be used, confirm that it supports the device you are planning to use. The supported devices are listed in the [Intel SoC FPGA Embedded Development Suite User Guide](#).

Other ways to program the flash devices are:

- Program Flash using a debugger (for example DS-5)
- Program Flash from U-Boot
- Program Flash from Linux (or other OS) console
- Program Flash by means of dedicated hardware

Related Information

[Intel® SoC FPGA Embedded Development Suite User Guide](#)

4.2.1.8. For QSPI and SD/MMC/eMMC Provide Flash Memory Reset

GUIDELINE: Ensure that the QSPI and SD/MMC/eMMC devices have a mechanism to be reset when the HPS is reset.

The QSPI and SD/MMC/eMMC flash devices can potentially be put in a state by software where the BootROM cannot access them successfully, which may trigger a boot failure on the next reset. This problem can occur because the HPS is reset, but the flash part is not reset.

It is therefore required to reset the QSPI and SD/MMC/eMMC boot flash devices each time there is an HPS reset (warm or cold).

Note that some devices do not have a reset pin. In such a case, you must power-cycle the flash by other means, for example with a MOSFET. Pay attention to minimum required reset pulse duration.

4.2.1.9. Selecting QSPI Flash Devices

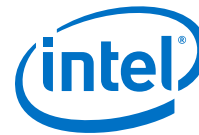
GUIDELINE: For bare-metal applications, avoid using a QSPI flash device larger than 16 MB

QSPI flash devices of 16 MB or less always support three-byte addressing. Therefore, they are accessible to the HPS Boot ROM. With such devices, you do not need to reset or power-cycle the flash when the HPS undergoes cold or warm reset.

GUIDELINE: With a QSPI device larger than 16 MB, use QSPI extended 4-byte addressing commands if supported by the device

Some QSPI flash devices support an extended command set, allowing the master to use four-byte addressing without switching to four-byte addressing mode. If you use the extended command set, you can leave the flash device in three-byte addressing mode, so that the Boot ROM can access it on the next reset cycle without resetting or power-cycling the flash device.

For detailed information about booting from QSPI, refer to [CV SoC and AV Soc QSPI Boot](#) on RocketBoards.org.



4.2.2. Configuration

The Cyclone V / Arria V SoC devices support two main type sof configuration flows:

- Traditional FPGA configuration
- HPS-initiated FPGA configuration

HPS-initiated configuration uses fast passive parallel (FPP) mode allowing the HPS to configure the FPGA using storage locations accessible to the HPS such as QSPI, SD/MMC and NAND flash. The FPGA configuration flows for the Cyclone V/Arria V SoC are the same for the Cyclone V/Arria V FPGA devices where an external configuration data source is connected to the control block in the FPGA.

4.2.2.1. Traditional Configuration

The traditional FPGA configuration flow is where the FPGA is configured by an external source such as JTAG, active serial or fast passive parallel.

4.2.2.2. HPS Initiated Configuration

When the device is powered and the HPS begin executing the software in the boot ROM, all the device I/O default to an input tri-state mode of operation. The boot ROM configures the dedicated boot I/O based on the sampled BSEL pins.

4.2.3. Reference Materials

Refer to the following reference materials for additional information.

Related Information

- [Intel® SoC FPGA Embedded Development Suite User Guide](#)
- [Support tab on Cyclone V SoCs](#)
Cyclone V SoC documentation
- [Support tab on Arria V SoCs](#)
Arria V SoC documentation
- [SoC Embedded Development Suite Getting Started Guides](#)
- [Golden System Reference Design \(GSRD\) User Manuals](#)
- [AN-709: HPS SoC Boot Guide - Cyclone V SoC Development Kit](#)

4.3. HPS Power Design Considerations

For design considerations and recommendations on power consumption and thermal analysis, SoC device pin connections, supply design and decoupling, refer to the Arria V and Cyclone V Design Guidelines.

The following sections are supplemental for SoC devices.

Related Information

[Arria V and Cyclone V Design Guidelines](#)

4.3.1. Early System and Board Planning

4.3.1.1. Early Power Estimation

Follow the guidelines in the **Early Power Estimation** website for using the Intel Quartus Prime software power analyzer spreadsheets.

In addition, consider the following guidelines for Cyclone V and Arria V SoC devices when using the EPE spreadsheet.

GUIDELINE: Use the Main worksheet to select “Maximum” for the Power Characteristics setting.

When estimating power consumption for the purposes of designing an adequate power supply that can meet the maximum power requirements across process, voltage and temperature (PVT), use the device maximum power characteristics.

GUIDELINE: Use the I/O worksheet to add HPS peripherals assigned to FPGA I/O.

This tab is where you describe the various configurations of I/O Elements (IOEs) in your application. Use the IO-IP tab to describe the controller IP behind each set of I/O.

For HPS peripherals assigned to FPGA I/O, add rows to the spreadsheet as necessary to describe the different HPS peripheral I/O characteristics in your design.

GUIDELINE: Use the HPS worksheet to select the Frequency, Application, and if applicable, the Application Mode for each CPU.

The Application/Application Mode settings for each CPU allow you to select from a list of industry standard benchmarks to model CPU utilization in your application. You can also select “Custom” for defining a unique set of CPU utilization parameters across the ALUs and cache memories.

GUIDELINE: Use the HPS worksheet to update the HPS SDRAM Type, Frequency and Width.

Note that the selection of SDRAM type also updates the I/O voltage for Bank 6A to 6B.

GUIDELINE: Use the HPS worksheet to update the HPS I/O Bank Voltage and Peripheral Usage

Before you select Peripheral voltage from the drop-down list, ensure that you have at least one HPS I/O Bank that is configured to the same voltage.

GUIDELINE: For Cyclone V SoC with L power option, apply the appropriate multiplication factor when calculating the total static power.

There is no L-power option in the EPE for Cyclone V, hence you need to calculate the total static power using the following steps:

1. Key in the design and resource utilization using the standard (non-L) part number.
2. Once total static power is obtained, apply a multiplication factor of 0.7 (for 25K-LE and 40K-LE devices) or 0.8 (for 85K-LE and 110K-LE devices) to calculate the lower static power for the L-power option devices.

Note: The multiplication factor only applies to total static power and not dynamic power.



Related Information

Early Power Estimators (EPE) and Power Analyzer

4.3.2. Design Considerations for HPS and FPGA Power Supplies for SoC FPGA devices

4.3.2.1. Consider the Need to Power Down the FPGA Portion While Keeping the HPS Running

GUIDELINE: Use a separate programmable regulator for FPGA supply to support powering down the FPGA while keeping the HPS running.

Cyclone V/Arria V SoC devices offer the ability to power down the FPGA while keeping the HPS running. To do this, the FPGA V_{CC} must be sourced from a programmable regulator that supports a control interface such as I²C. The Cyclone V SoC Development Kit is an example of a development board that supports this feature. You can find information about the Cyclone V SoC Development Kit at [Cyclone V SoC Development Kit and Intel SoC FPGA Embedded Development Suite](#).

You can refer to the [Cyclone V SoC Smart Configuration](#) design example to understand how to control the FPGA power supply regulator using the I²C connection from the HPS.

4.3.2.2. Consider Desired HPS Boot Clock Frequency

Cyclone V / Arria V SoC devices support a HPS boot clock from 10-50 MHz in PLL bypass mode, and up to 400MHz in PLL Locked mode. During power up or cold reset, the boot ROM samples the value of the $CSEL$ pins and if needed, configure the HPS PLL to provide a faster boot clock frequency.

Refer to the table with $CSEL$ options and corresponding external oscillator frequency in the "Boot and Configuration" appendix of the appropriate *Hard Processor System Technical Reference Manual*.

Related Information

- "Boot and Configuration" appendix of the *Cyclone V Hard Processor System Technical Reference Manual*
- "Boot and Configuration" appendix of the *Arria V Hard Processor System Technical Reference Manual*

4.3.3. Pin Connection Considerations for Board Designs

4.3.3.1. Device Power-Up

Power-Up and Power-Down Sequencing

Cyclone V/ Arria V SoC devices have the following additional power rails to consider for power sequencing.

- VCC_HPS
- VCCPD_HPS
- VCCIO_HPS

- VCCRSTCLK_HPS
- VCCPLL_HPS
- VCC_AUX_SHARED

Refer to "Power-Up Sequence" in the "Power Management" chapter of Volume 1: *Device Interfaces and Integration* in the *Cyclone V* or *Arria V* Device Handbook.

GUIDELINE: Consider ramp times for maximum transient currents on supplies when designing the Power Distribution Network (PDN).

When using the PDN Tool to calculate the required target impedance of your application's PDN for the core fabric's VCC supply, model the ramp time of the maximum transient current on VCC using the Core Clock Frequency and Current Ramp Up Period parameters. This procedure relaxes the target impedance requirements relative to the default step function analysis, resulting in a more efficient PDN with fewer decoupling capacitors.

Initial transient current estimates can be obtained from the EPE Spreadsheet, and more accurate analysis is possible with the Power Analyzer Power Analysis Tool in Intel Quartus Prime when your design is closer to completion.

Refer to [AN 750: Using the Altera PDN Tool to Optimize Your Power Delivery Network Design](#).

Related Information

- [Arria V and Cyclone V Design Guidelines](#)
- [Cyclone V Device Handbook](#)
- [Arria V Device Handbook](#)

4.3.4. Power Analysis and Optimization

Follow the guidelines in the Power Analysis and Optimization section of the [Arria V and Cyclone V Design Guidelines](#). In addition, consider the following options for the HPS portion of the device.

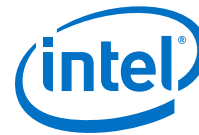
Processor and memory clock speeds

The biggest contribution to power consumption from the HPS is the processor clock speed and the type, size and speed of the external SDRAM program memory. Careful selection of these system parameters to satisfy the functional and performance requirements of the application helps to minimize system power consumption.

CPU Standby Modes and Dynamic Clock Gating

CPU standby modes and dynamic clock gating logic can be utilized throughout the MPU subsystem. Each CPU can be placed in standby mode, Wait for Interrupt, or Wait for Event mode to further minimize power consumption.

For more information on standby modes, refer to the [Cortex-A9 Technical Reference Manual \(revision r2p0\)](#). Power Optimization Examples are available on the [Design Examples](#) web page.



Managing Peripheral Power

When configuring the HPS component in Platform Designer (Standard), enable only those peripherals your application uses. Configure the peripherals for the lowest clock speed while maintaining functional and performance requirements. Additional power can be saved under software control by placing inactive peripherals in reset and gating off their clock sources.

Managing Power by Shutting Down Supplies

Cyclone V SoC and Arria V SoC support the ability to power down the FPGA portion of the device, while keeping the HPS running. Refer to the [Cyclone V SoC Smart Configuration](#) design example on how to control the FPGA power supply regulator using the I²C connection from the HPS.

4.4. Boundary Scan for HPS

GUIDELINE: Ensure that the HPS is powered up and held in reset before performing a boundary scan test of the FPGA and HPS I/O.

The HPS JTAG does not support boundary scan tests (BST). To perform boundary scan testing on HPS I/O pins, you must use the FPGA JTAG.

4.5. Design Guidelines for HPS Interfaces

This section outlines the design guidelines for HPS Interfaces like EMAC PHY, USB, QSPI, SD/MMC, NAND Flash, UART, I²C and SPI.

4.5.1. HPS EMAC PHY Interfaces

When configuring an HPS component for EMAC peripherals within Platform Designer (Standard), you must select from one of the following supported PHY interfaces for each EMAC instance:

- Reduced Gigabit Media Independent Interface (RGMI) using dedicated I/O
- Media Independent Interface (MII) interface to FPGA fabric
- Gigabit Media Independent Interface (GMII) interface to FPGA fabric

Any combination of supported PHY interface types can be configured across multiple HPS EMAC instances.

GUIDELINE: For RGMI using HPS Dedicated I/O, develop an early I/O floor-planning template design to ensure that there are enough HPS Dedicated I/O to accommodate the chosen PHY interfaces in addition to other HPS peripherals planned for HPS Dedicated I/O usage.

Note: For guidelines on configuring the HPS component, refer to the "Introduction to the HPS Component" chapter of the *Cyclone V or Arria V Hard Processor System Technical Reference Manual*.

It is possible to adapt the MII/GMII PHY interfaces exposed to the FPGA fabric by the HPS component to other PHY interface standards—such as RMII, RGMI, SGMII, MII and GMII—by using soft adaptation logic in the FPGA and features in the general-purpose FPGA I/O and transceiver FPGA I/O.

GUIDELINE: When selecting a PHY device, consider the desired Ethernet rate, available I/O and available transceivers; PHY devices that offer the skew control feature; and device driver availability.

Note: Refer to the device drivers available for your OS of choice or the Linux device driver provided with the Cyclone V/ Arria V SoC development kit (Golden System Reference Design)

The Cyclone V/Arria V SoC Hard Processor System (HPS) can connect its embedded Ethernet MAC (EMAC) PHY interfaces directly to industry standard Gigabit Ethernet PHYs using the RGMII interface at any supported I/O voltage using the HPS Dedicated I/O pins. These voltages typically include 1.8V, 2.5V and 3.0V. If the HPS Dedicated I/O pins are used for the PHY interface, then no FPGA routing resources are used and timing is fixed, simplifying timing on the interface. This document describes the design guidelines for RGMII, the most typical interfaces.

You can also connect PHYs to the HPS EMACs through the FPGA fabric using the GMII and MII bus interfaces for Gigabit and 10/100 Mbps access respectively. A GMII-to-SGMII adapter is also available to automatically adapt to transceiver-based SGMII optical modules.

Note: Due to an erratum in the Cyclone V/Arria V SoC device, the RMII PHY interface is not supported when routing through the HPS Dedicated I/O. RMII interface however is supported when routing through the FPGA fabric.

Related Information

- ["Introduction to the HPS Component" chapter of the Cyclone V Hard Processor System Technical Reference Manual](#)
- ["Introduction to the HPS Component" chapter of the Arria V Hard Processor System Technical Reference Manual](#)
- [Golden System Reference Design \(GSRD\) User Manuals](#)

4.5.1.1. PHY Interfaces Connected Through HPS Dedicated I/O

This section discusses design considerations for RGMII PHY interface through the HPS Dedicated I/O.

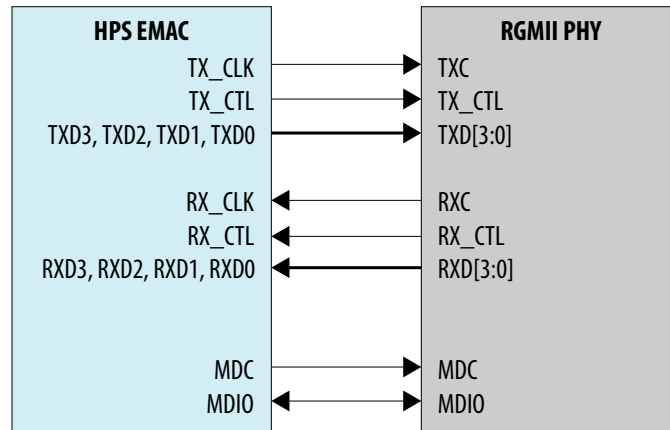
4.5.1.1.1. RGMII

Reduced Gigabit Media Independent Interface (RGMII) (Reduced GMII) is the most common interface as it supports 10 Mbps, 100 Mbps, and 1000 Mbps connection speeds at the PHY layer. RGMII uses four-bit wide transmit and receive datapaths, each with its own source synchronous clock. All transmit data and control signals are source synchronous to TX_CLK, and all receive data and control signals are source synchronous to RX_CLK.

For all speed modes, TX_CLK is always sourced by the MAC, and RX_CLK is always sourced by the PHY. In 1000 Mbps mode, TX_CLK and RX_CLK are 125 MHz, and Dual Data Rate (DDR) signaling is used. In

10 Mbps and 100 Mbps modes, TX_CLK and RX_CLK are 2.5 MHz and 25 MHz, respectively, and rising edge Single Data Rate (SDR) signaling is used.

Figure 5. RGMII



I/O Pin Timing

This section addresses RGMII interface timing from the perspective of meeting requirements in the 1000 Mbps mode. The interface timing margins are most demanding in 1000 Mbps mode, thus it is the only scenario we consider here.

At 125 MHz, the period is 8 ns, but because both edges are used, the effective period is only 4 ns. The TX and RX busses are completely separate and source synchronous, simplifying timing. The RGMII spec calls for CLK to be delayed from DATA at the receiver in either direction by a minimum 1.0 ns and a maximum 2.6 ns.

In other words, the TX_CLK from the MAC to the PHY must be delayed from the output to the PHY input and the RX_CLK from the PHY output to the MAC input. The signals are transmitted source synchronously within the +/-500 ps RGMII skew spec in each direction as measured at the output pins. The minimum delay needed in each direction is 1ns but it is recommended to target a delay of 1.5 ns to 2 ns to keep timing margin.

Transmit path setup/hold

Only setup and hold for TX_CLK to TX_CTL and TXD[3:0] matter for transmit. The Cyclone V/Arria V HPS Dedicated I/O does not feature programmable delay.

For TX_CLK from the Cyclone V/Arria V SoC, you must introduce the 1.0 ns PHY minimum input setup time in the RGMII spec. It is strongly recommended to increase this to delay to 1.5 ns to 2.0 ns. Many PHYs offer programmable skew, and some support RGMII 2.0 which defaults to skew enabled on both transmit and receive datapaths.

Between PHY delay and FPGA I/O delay features, you must ensure either 2 ns of delay to CLK versus CTL and D[3:0] or 1.2 ns typical minimum setup skew typical of most PHYs. Consult the datasheet for your PHY vendor for more details.

GUIDELINE: Ensure your design includes the necessary Quartus settings to configure the HPS EMAC outputs for the required delays.

On the Cyclone V/Arria V SoC Development Kit and the associated Golden Hardware Reference Design (the GHRD is the hardware component of the GSRD) PHY skew is implemented with the Microchip* (Micrel*) KSZ9021RN PHY. Refer to the `hps_common_board_info.xml` file and PHY driver code in the Golden System Reference Design (GSRD).

Receive path setup/hold

Only setup and hold for `RX_CLK` to `RX_CTL` and `RXD[3:0]` are necessary to consider for receive timings. For Cyclone V/Arria V SoC HPS Dedicated I/O no other consideration on the PHY side or board trace delay is required.

GUIDELINE: Hardware developers should specify the required FPGA skew so that software developers can add the skew to the device driver code.

The `hps_common_board_info.xml` file is used to compile the Linux device tree for the Cyclone V or Arria V SoC GSRD.

4.5.1.2. PHY Interfaces Connected Through FPGA I/O

Using FPGA I/O for an HPS EMAC PHY interface can be helpful when there is not enough HPS Dedicated I/O left to accommodate the PHY interface or when you want to adapt to a PHY interface not natively supported by the HPS EMAC.

GUIDELINE: Specify the PHY interface transmit clock frequency when configuring the HPS component within Platform Designer (Standard).

For either GMII or MII, including adapting to other PHY interfaces, specify the maximum transmit path clock frequency for the HPS EMAC PHY interface: 125 MHz for GMII, 25 MHz for MII. This configuration results in the proper clock timing constraints being applied to the PHY interface transmit clock upon Platform Designer (Standard) system generation.

Related Information

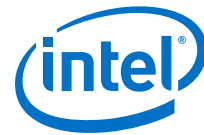
- [Embedded Peripherals IP User Guide](#)
- [Cyclone V RGMII Example Design](#)

4.5.1.2.1. GMII/MII

MII and GMII are only available in Cyclone V/Arria V SoC by driving the EMAC signals into the FPGA core routing logic and then ultimately to FPGA I/O pins or to internal registers in the FPGA core.

GUIDELINE: Apply timing constraints and verify timing with Timing Analyzer.

Because routing delays can vary widely in the FPGA core and I/O structures, it is important to read the timing reports, and especially for GMII, create timing constraints. GMII has a 125 MHz clock and is single data rate unlike RGMII. GMII does not have the same considerations for CLK-to-DATA skew though; its signals are automatically centered by design by being launched with the negative edge and captured with the rising edge.



GUIDELINE: Register interface I/O at the FPGA I/O boundary.

With core and I/O delays easily exceeding 8 ns, it is recommended to register these buses in each direction in I/O Element (IOE) registers, so they remain aligned as they travel across the core FPGA logic fabric. On the transmit data and control, maintain the clock-to-data/control relationship by latching these signals on the falling edge of the `emac[0,1,2]_gtx_clk` output from the HPS EMAC. Latch the receive data and control at the FPGA I/O inputs on the rising edge of the `RX_CLK` sourced by the PHY.

GUIDELINE: Consider transmit timing in MII mode.

MII is 25 MHz when the PHY is in 100 Mbps mode and 2.5 MHz when the PHY is in 10 Mbps mode, so the shortest period is 40 ns. The PHY sources the clock for both transmit and receive directions. Because the transmit timing is relative to the `TX_CLK` clock provided by the PHY, the turnaround time may be of concern, but this is usually not an issue due to the long 40-ns period.

Note: The transaction is routed through the FPGA, then out for the data. The round-trip delay must be less than 25 ns, because there is a 15-ns input setup time. The transmit data and control are launched into the FPGA fabric by the HPS EMAC transmit path logic on the negative edge of the PHY-sourced `TX_CLK`, which removes 20 ns of the 40-ns clock-to-setup timing budget.

With the round trip clock path delay on the data arrival timing incurring PHY-to-SoC board propagation delay plus the internal path delay from the SoC pin to and through the HPS EMAC transmit clock mux taking away from the remaining 20-ns setup timing budget, it may be necessary to retime the transmit data and control to the rising edge of the `phy_txclk_o` clock output registers in the FPGA fabric for MII mode transmit data and control.

4.5.1.2.2. Adapting to RGMII

It is possible to adapt the GMII HPS EMAC PHY signals to an RGMII PHY interface at the FPGA I/O pins using logic in the FPGA. While it is possible to design custom logic for this adaptation, this section describes using Platform Designer (Standard) adapter IP.

GUIDELINE: Use the GMII-to-RGMII Adapter IP available in Platform Designer (Standard).

Configure the HPS component in Platform Designer (Standard) for an EMAC as "FPGA" I/O instance. Do not export the resulting HPS component GMII signals in Platform Designer (Standard). Instead, add the Intel HPS GMII to RGMII Converter to the Platform Designer (Standard) subsystem and connect to the HPS component's GMII signals. The GMII to RGMII Converter uses the Intel HPS EMAC Interface Splitter in Platform Designer (Standard) to split out the `emac` conduit from the HPS component for use by the GMII to RGMII Converter. See the [Embedded Peripherals IP User Guide](#) for information on how to use the Intel HPS GMII to RGMII Converter.

GUIDELINE: Provide a glitch-free clock source for the 10/100 Mbps modes.

In an RGMII PHY interface, the `TX_CLK` is always sourced by the MAC, but the HPS component's GMII interface expects `TX_CLK` to be provided by the PHY device in 10/100 Mbps modes. The GMII to RGMII adaptation logic must provide the 2.5/25 MHz `TX_CLK` on the GMII's `emac[0,1]_tx_clk_in` input port, and the switch between 2.5 MHz and 25 MHz must be accomplished in a glitch-free manner as

required by the HPS EMAC. An FPGA PLL can be used to provide the 2.5 MHz and 25 MHz TX_CLK along with an ALTCLKCTRL block to select between counter outputs glitch-free.

Note: Refer to the [Cyclone V RGMII Example Design](#) for hardware and software example of this implementation.

4.5.1.2.3. Adapting to RMII

It is possible to adapt the MII HPS EMAC PHY signals to an RMII PHY interface at the FPGA I/O pins using logic in the FPGA.

GUIDELINE: Provide a 50MHz REF_CLK source.

An RMII PHY uses a single 50 MHz reference clock (REF_CLK) for both transmit and receive data and control. Provide the 50 MHz REF_CLK either with a board-level clock source, a generated clock from the FPGA fabric, or from a PHY capable of generating the REF_CLK.

GUIDELINE: Adapt the transmit and receive data and control paths.

The HPS EMAC PHY interface exposed in the FPGA fabric is MII, which requires separate transmit and receive clock inputs of 2.5 MHz and 25 MHz for 10 Mbps and 100 Mbps modes of operation, respectively. Both transmit and receive datapaths are 4-bits wide. The RMII PHY uses the 50 MHz REF_CLK for both its transmit and receive datapaths and at both 10 Mbps and 100 Mbps modes of operation. The RMII transmit and receive datapaths are 2-bits wide. At 10 Mbps, transmit and receive data and control are held stable for 10 clock cycles of the 50 MHz REF_CLK. You must provide adaptation logic in the FPGA fabric to adapt between the HPS EMAC MII and external RMII PHY interfaces: 4-bits @ 25 MHz/2.5 MHz to/from 2-bits@ 50 MHz, 10x oversampled in 10 Mbps mode.

GUIDELINE: Provide a glitch-free clock source on the HPS EMAC MII tx_clk_in clock input.

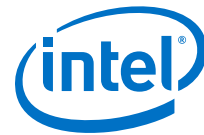
The HPS component's MII interface requires a 2.5/25 MHz transmit clock on its emac[0,1,2]_tx_clk_in input port, and the switch between 2.5 MHz and 25 MHz must be done glitch free as required by the HPS EMAC. An FPGA PLL can be used to provide the 2.5 MHz and 25 MHz transmit clock along with an ALTCLKCTRL block to select between counter outputs glitch-free.

Related Information

[Embedded Peripherals IP User Guide](#)

4.5.1.2.4. Adapting to SGMII

It is possible to adapt the GMII HPS EMAC PHY signals to an SGMII PHY interface at the FPGA transceiver I/O pins using logic in the FPGA and the multi-gigabit transceiver I/O. While it is possible to design custom logic for this adaptation, this section describes using Platform Designer (Standard) adapter IP.

**GUIDELINE: Use the Intel HPS GMII to TSE 1000BASE-X/SGMII PCS Bridge, available in Platform Designer (Standard).**

Configure the HPS component in Platform Designer (Standard) for an EMAC as "FPGA" I/O instance. Do not export the resulting HPS component GMII signals in Platform Designer (Standard). Instead, add the Intel HPS GMII to TSE 1000BASE-X/SGMII PCS Bridge to the Platform Designer (Standard) subsystem and connect to the HPS component's GMII signals. The bridge uses the Intel HPS EMAC Interface Splitter in Platform Designer (Standard) to split out the `emac` conduit from the HPS component for use by the GMII bridge. The bridge instantiates the Intel Triple Speed Ethernet (TSE) MAC, configured in 1000 BASE-X/SGMII PCS PHY-only mode (i.e., no soft MAC component). See the [Embedded Peripherals IP User Guide](#) for information on how to use the Intel HPS GMII to TSE 1000BASE-X/SGMII PCS Bridge.

Note: Refer to the [Cyclone V SGMII Example Design](#) for hardware and software example of this implementation.

4.5.1.2.5. MDIO

The MDIO PHY management bus has two signals per MAC: MDC and MDIO. MDC is the clock output, which is not free running. At 2.5 MHz, it has a 400-ns minimum period. MDIO is a bi-directional data signal with a High-Z bus turnaround period.

When the MAC writes to the PHY, the data is launched on the falling edge, meaning there is $200\text{ ns} - 10\text{ ns} = 190\text{ ns}$ for flight time, signal settling, and setup at the receiver. Because data is not switched until the following negative edge, there is also 200 ns of hold time. These requirements are very easy to meet with almost any board topology. When the MAC reads from the PHY, the PHY is responsible for outputting the read data from 0 to 300 ns back to the MAC, leaving 100 ns less 10 ns setup time, or 90 ns for flight time, signal settling, and setup at the receiver. This requirement is also very easy to meet.

GUIDELINE: Implement pull-up resistor on board for MDC/MDIO.

Both signals require an external pull-up resistor, typically 1K but PHY data-sheets may vary.

GUIDELINE: Ensure interface timing is met.

There is a 10ns setup and hold requirement for MDIO for data with respect to MDC.

4.5.1.3. Common PHY Interface Design Considerations**4.5.1.3.1. Signal Integrity****GUIDELINE: Use appropriate board-level termination on PHY outputs.**

Not many PHYs offer I/O tuning for their outputs to the Cyclone V/Arria V SoC, so it is wise to double check this signal path with a simulator. Place a series resistor on each signal near the PHY output pins to reduce the reflections if necessary.

GUIDELINE: Minimize reflections at PHY TX_CLK and EMAC RX_CLK inputs to prevent double-clocking.

Be cognizant if the connection is routed as a "T" as signal integrity must be maintained such that no double-edges are seen at REF_CLK loads. Ensure reflections at REF_CLK loads are minimized to prevent double-clocking.

GUIDELINE: Use a Signal Integrity (SI) simulation tool.

It is fairly straightforward to run SI simulations on these unidirectional signals. These signals are almost always point-to-point, so simply determining an appropriate series resistor to place on each signal is usually enough. Many times, this resistor is not necessary, but the device drive strength and trace lengths as well as topology should be studied when making this determination.

4.5.2. USB Interface Design Guidelines

The Cyclone V/Arria V SoC Hard Processor system can connect its embedded USB MACs directly to industry-standard USB 2.0 ULPI PHYs using the HPS Dedicated I/O that support 1.8V, 2.5V, 3.0V and 3.3V I/O standards. No FPGA routing resources are used and timing is fixed, which simplifies design. This guide describes the design guidelines covering all supported speeds of PHY operation: High-Speed (HS) 480 Mbps, Full-Speed (FS) 12 Mbps, and Low-Speed (LS) 1.5 Mbps.

Note: In Cyclone V SoC U19 package (484 pins) only one USB controller is available.

GUIDELINE: Design the board to support both USB PHY modes where the device supplies the clock versus where an external clock is the source.

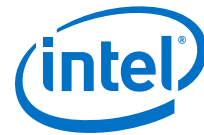
The interface between the ULPI MAC and PHY on the Cyclone V/Arria V SoC consists of DATA[7:0], DIR and NXT from the MAC to the PHY and STP from the MAC to the PHY. Lastly a static clock of 60 MHz is driven from the PHY and is required for operation, including some register accesses from the HPS to the USB MAC. Ensure the PHY manufacturer recommendations for RESET and power-up are followed.

GUIDELINE: Ensure that the USB signal trace lengths are minimized.

At 60 MHz, the period is 16.67 ns and in that time, for example, the clock must travel from the external PHY to the MAC and then the data and control signals must travel from the MAC to the PHY. Because there is a round-trip delay, the maximum length of the CLK and ULPI signals are important. Based on timing data the maximum length is recommended to be less than 7 inches. This is based on a PHY with a 5 ns T_{CO} specification. If the specification is slower the total length must be shortened accordingly.

GUIDELINE: Ensure that signal integrity is considered.

Signal integrity is also important but mostly on the CLK signal driven from the PHY to the MAC in the HPS subsystem. Because these signals are point-to-point with a maximum length, they can usually run unterminated but it is recommended to simulate the traces to make sure the reflections are minimized. Using the 50-ohm output setting from the FPGA is typically recommended unless the simulations show otherwise. A similar setting should be used from the PHY vendor if possible.

**GUIDELINE: Design properly for OTG operation, when applicable.**

When On-the-Go (OTG) functionality is used, the SoC can become a host or endpoint. When in host mode consider the power delivery, such as when you are supporting a USB Flash drive, or potentially a USB Hard Drive. These power requirements and reverse currents must be accounted for, typically by using external diodes and current limiters such as those used on the Cyclone V SoC or Arria V SoC development kits.

4.5.3. QSPI Flash Interface Design Guidelines

Up to four QSPI chip selects can be used with Cyclone V/Arria V SoC. The device can boot only from QSPI connected to the chip select zero.

GUIDELINE: Ensure that the QSPI_SS signals are used in numerical order.

Intel Quartus Prime assumes that the QSPI_SS signals are used in order. It is not possible to use SS0 and SS2, for example, without using SS1.

Note: Refer to [Supported Flash Devices for Cyclone V and Arria V SoC](#) for a list of supported QSPI devices. RocketBoards.org also provides useful information at [GSRD v13.1 - Booting from QSPI](#) and [GSRD v13.1 - Programming QSPI Flash](#).

GUIDELINE: If your design uses QSPI flash with 4-byte addressing, design the board to ensure that the QSPI flash is reset or power-cycled whenever the HPS is reset.

The HPS boot ROM on Cyclone V and Arria V runs in 3-byte address mode by default. If the QSPI flash is switched to 4-byte addressing during operation, ensure that it is returned to its default 3-byte addressing mode whenever the HPS is reset. Otherwise, the HPS cannot boot from or access the QSPI flash memory device.

You can switch the QSPI to 3-byte addressing mode using one of the following methods:

- If the QSPI device has a reset pin, assert the reset signal every time the HPS device is reset.
- If the QSPI device does not have a reset pin, power-cycle the QSPI device every time the HPS device is reset.

The [CV SoC and AV Soc QSPI Boot](#) page of RocketBoards.org offers recommendations for implementing the reset signal to the QSPI flash. For additional information, refer to "Selecting QSPI Flash Devices" and "For QSPI and SD/MMC/eMMC Provide Flash Memory Reset".

Related Information

- [Selecting QSPI Flash Devices](#) on page 32
- [For QSPI and SD/MMC/eMMC Provide Flash Memory Reset](#) on page 32
- [Supported Flash Devices for Cyclone V SoC and Arria V SoC](#)

4.5.4. SD/MMC and eMMC Card Interface Design Guidelines

GUIDELINE: Include a voltage translator if you plan on support the SD 1.8V feature. A translator is necessary because the HPS I/O cannot change voltage levels dynamically like the SD card.

SD cards initially operate at 3.3V, and some cards can switch to 1.8V after initialization. In addition, some MMC cards can operate at both 1.8V as well as 3.3V. Because the `BSEL` values are constant during the boot process, transceivers are required to support level-shifting and isolation for cards that can operate at 1.8 V.

Follow the guidelines in "Voltage Switching" in the "SD/MMC Controller" chapter of the appropriate *Hard Processor System Technical Reference Manual*. Some MMC cards can operate with only 1.8V I/O operation and initial operation at 3.3V is not required. In this situation, a level shifter is not needed.

Table 8. Level Shifting Requirements

HPS I/O Bank Voltage	SD Card Voltage	Level Shifter Needed?
3.3V	3.3V	No
3.3V	1.8V	Yes
1.8V	3.3V	Yes
1.8V	1.8V	Yes

GUIDELINE: Ensure that timing is considered for initial ID mode and data transfer mode as well as normal operation.

SD cards initially operate at 400 KHz maximum when they are going through the ID process. After that there is a data transfer mode, during which the clock can operate up to 12.5 MHz. In normal operation, the clock can operate up to 50 MHz. The Boot ROM takes care to ensure that clocking is properly configured during ID and transfer modes.

Refer to the "CSEL Settings for the SD/MMC Controller" table in the "Bootling and Configuration" appendix of the appropriate *Hard Processor System Technical Reference Manual*.

GUIDELINE: Ensure that the SD/MMC card is reset whenever the HPS is reset.

To allow the system to boot from SD/MMC, whenever the HPS is reset, ensure that the SD/MMC card is also reset. This ensures that the memory card is in the state expected by the boot code.

Related Information

- [Voltage Switching \(Cyclone V\)](#)
Level shifting guidelines for 1.8 V SD operation in the Cyclone V HPS
- [Voltage Switching \(Arria V\)](#)
Level shifting guidelines for 1.8 V SD operation in the Arria V HPS
- [CSEL Settings for the SD/MMC Controller](#)
Table in the "Bootling and Configuration" appendix of the *Cyclone V Hard Processor System Technical Reference Manual*



- [CSEL Settings for the SD/MMC Controller](#)
Table in the "Boot and Configuration" appendix of the *Arria V Hard Processor System Technical Reference Manual*

4.5.5. NAND Flash Interface Design Guidelines

GUIDELINE: Ensure that the selected NAND flash device is an 8-bit ONFI 1.0 (or later) compliant device.

The NAND flash controller in the HPS requires:

- The external flash device to be 8-bit ONFI 1.0 compliant
- Single-level cell (SLC) or multi-level cell (MLC)
- Page size: 512 bytes, 2 KB, 4 KB or 8 KB
- Pages per block: 32, 64, 128, 256, 384 or 512
- Error correction code (ECC) sector size can be programmed to 512 bytes (for 4-, 8- or 16-bit correction) or 1024 bytes (24-bit correction)

You cannot export the NAND interface to FPGA.

Note: Refer to [Supported Flash Devices for Cyclone V and Arria V SoC](#) for a list of supported NAND devices.

4.5.6. UART Interface Design Guidelines

GUIDELINE: Properly connect flow control signals when routing the UART signals through the FPGA fabric.

When routing UART signals through the FPGA, the flow control signals are available. If flow control is not being used, connect the FPGA signals as shown in the following table.

Table 9. UART Connections to Disable Flow Control

Signal	Direction	Connection
CTS	Input	Low
DSR	Input	High
DCD	Input	High
RI	Input	High
DTR	Output	No-connect
RTS	Output	No-connect
OUT1_N	Output	No-connect
OUT2_N	Output	No-connect

4.5.7. I²C Interface Design Guidelines

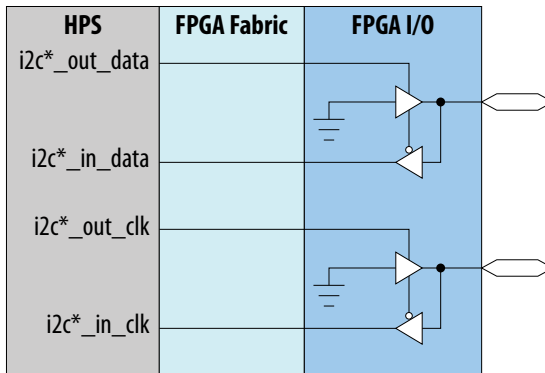
GUIDELINE: Instantiate the open-drain buffer when routing I²C signals through the FPGA fabric.

When routing I²C signals through the FPGA, note that the I²C pins from the HPS to the FPGA fabric (`i2c*_out_data`, `i2c*_out_clk`) are not open-drain and are logic level inverted. Thus, when you want to drive a logic level zero onto the I²C bus, these pins are high. This implementation is useful as they can be used to tie to an output enable of a tri-state buffer directly. You must use the `altioobuf` to implement the open-drain buffer.

GUIDELINE: Ensure that the pull-ups are added to the external SDA and SCL signals in the board design.

Because the I²C signals are open drain, pull-ups are required to make sure that the bus is pulled high when no device on the bus is pulling it low.

Figure 6. I²C Wiring to FPGA pins



4.5.8. SPI Interface Design Guidelines

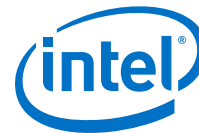
GUIDELINE: Consider routing SPI slave signals to FPGA fabric

Due to an erratum in the Cyclone V/Arria V SoC device, the SPI output enable is not connected to the SPI HPS pins. As a result, the HPS `SPIS_TXD` pin cannot be tri-stated by setting the `slv_oe` bit (bit 10) in the `ctrlr0` register to 1.

Routing the SPI Slave signals to FPGA exposes the output enable signal and allows you to connect it to an FPGA tri-state pin.

GUIDELINE: If your SPI peripheral requires the SPI master slave select to stay low during the entire transaction period, consider using GPIO as slave select, or configure the SPI master to assert slave select during the transaction.

By default, the SPI master is configured with `ctrlr0.scph = 0` and `ctrlr0.scpol = 0`, which makes the Cyclone V or Arria V HPS SPI master deassert the slave select signal between each data word. Set `ctrlr0.scph` to 1 and `ctrlr0.scpol` to 1, to make the SPI master assert slave select for the entire duration of the transfer.



Alternatively, consider routing the SPI master peripheral to FPGA, and using GPIO to control the slave select signal.

Note: If you use this method, refer to the following Knowledge Base articles:

- [Why does connecting HPS peripheral clocks to external pins via FPGA logic cause Quartus fitter errors?](#)
- [Why does the HPS SPI Master fail when slave select is mapped to GPIO?](#)

Related Information

- [ctrlr0](#)
For details about the `ctrlr0.scph` and `ctrlr0.scpol` bits in the Cyclone V HPS, refer to "ctrlr0" in the "SPI Master" chapter of the *Cyclone V Hard Processor System Technical Reference Manual*.
- [ctrlr0](#)
For details about the `ctrlr0.scph` and `ctrlr0.scpol` bits in the Arria V HPS, refer to "ctrlr0" in the "SPI Master" chapter of the *Arria V Hard Processor System Technical Reference Manual*.

5. Embedded Software Design Guidelines for SoC FPGAs

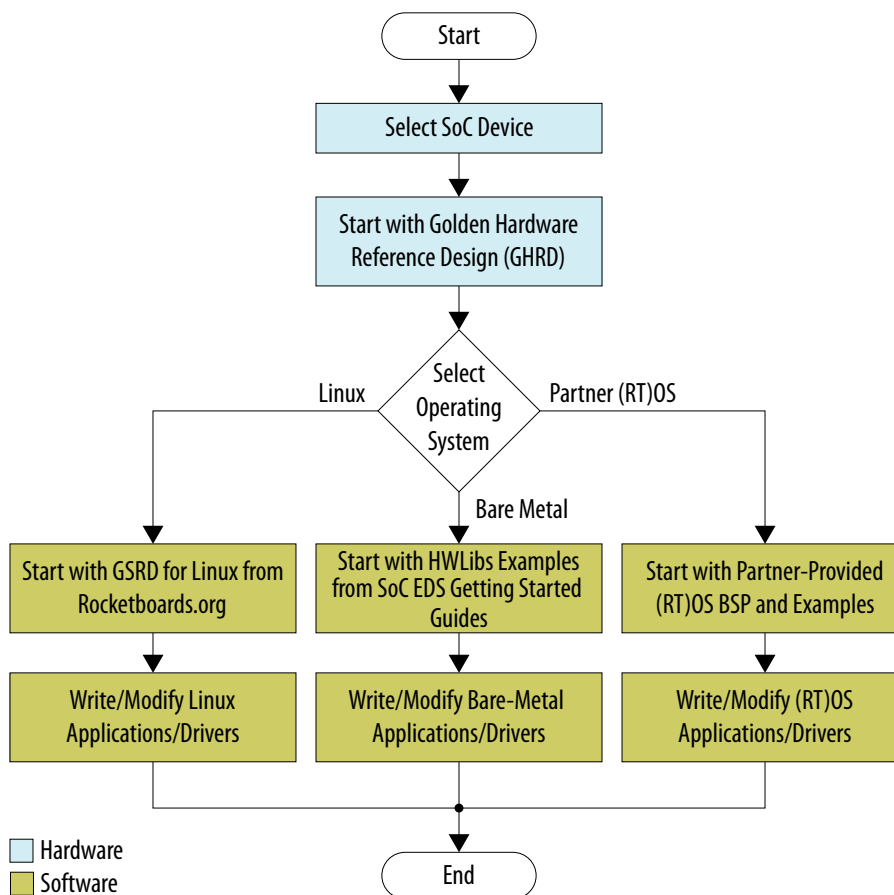
5.1. Embedded Software for HPS: Design Guidelines

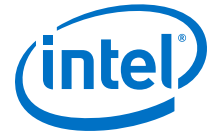
5.1.1. Assembling the Components of Your Software Development Platform

To successfully build your software development platform, Intel recommends that you start with a baseline project, which is a known good configuration of an HPS system. Then modify the baseline project to suit your end application.

The following diagram presents the recommended procedure to determine the software development platform components.

Figure 7. Assembling Software Development Platform





In summary, the process consists of following steps:

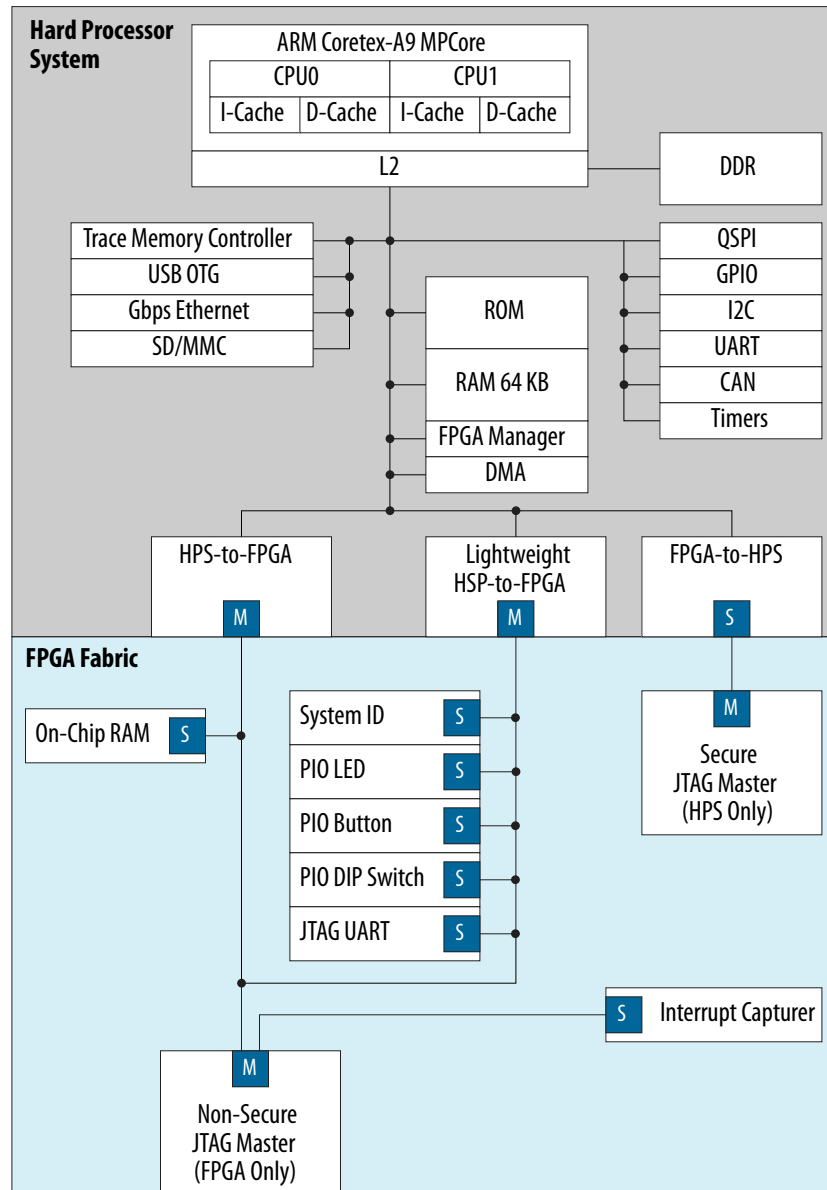
1. Select the desired device
2. Use the GHRD as a hardware project starting point
3. Select the operating system: bare metal, Linux* or partner real-time operating system (RTOS)
4. Write or update end applications as well as drivers

5.1.1.1. Golden Hardware Reference Design

The Golden Hardware Reference Design is an Intel Quartus Prime project that contains a full HPS design for the Cyclone V SoC / Arria V SoC Development Kit. The GHRD has connections to a boot source, SDRAM memory and other peripherals on the development board.

For every new released version of SoC EDS, the GHRD is included in the SoC EDS tools. The GHRD is regression tested with every major release of the Intel Quartus Prime Design Software and includes the latest bug fixes for known hardware issues. The GHRD serves as a known good configuration of an SoC FPGA hardware system.

Figure 8. Cyclone V / Arria V SoC Golden Hardware Reference Design Overview



The GHRD has a minimal set of peripherals in the FPGA fabric, because the HPS provides a substantial selection of peripherals. HPS-to-FPGA and FPGA-to-HPS interfaces are configured to a 64-bit data width.

GUIDELINE: Intel recommends that you use the latest GHRD as a baseline for new SoC FPGA hardware projects. You may then modify the design to suit your application ends.

The GHRD can be obtained from:



- The [GSRD for Linux page](#) for the latest version, which is the best known configuration
- `<SoC EDS installation directory>\examples\hardware\cv_soc_devkit_ghrd` - for the version supported by the corresponding SoC EDS version, used as a basis for the provided HWLibs design examples.

5.1.2. Selecting an Operating System for Your Application

5.1.2.1. Linux or RTOS

There are a number of operating systems that support the Cyclone V SoC and Arria V SoC, including Linux and several real-time operating systems (RTOSs). For more information on Intel's SoC Partner OS ecosystem, visit the [Ecosystem](#) tab of the **Intel FPGAs** page.

Partner OS providers offer board support packages and commercial support for the SoC FPGA devices. The Linux community also offers board support packages and community support for the SoC FPGA device.

There are many factors that go into the selection of an operation system for SoC FPGAs including the features of the operating system, licensing terms, collaborative software projects and framework based on the OS, available device drivers and reference software, in-house legacy code and familiarity with the OS, real-time requirements of your system, functional safety and other certifications required for your application.

To select an appropriate OS for your application, it is recommended that you familiarize yourself with the features and support services offered by the commercial and open source operating systems available for the SoC FPGA. Intel's OS partners, industry websites are a good source of information you can use to help make your selection.

There are a number of misconceptions when it comes to real-time performance of operating systems versus bare metal applications. For a Cortex A-class of processor there are a number of features that real-time operating systems provide that make efficient use of the processor's resources in addition to the facilities provided to manage the run-time application. You may find that these efficiencies result in sufficient real-time performance for your application, enabling you to inherit a large body of available device drivers, middleware packages, software applications and support services. It is important to take this account when selecting an operating system.

5.1.2.2. Bare Metal

The HPS can be used in a bare-metal configuration (without an OS) and Intel offers the HWLibs (Hardware Libraries) that consist of both high-level APIs, and low-level macros for most of the HPS peripherals.

However, to use a bare metal application for the HPS, you must be familiar with developing run time capabilities to ensure that your bare metal application makes efficient use of resources available in your MPU subsystem.

For example:

- A typical bare-metal application uses only a single core, you must develop run time capabilities to manage process between both cores and the cache subsystem if you want to fully utilize the MPU subsystem.
- As your application increases in complexity you may need to build capabilities to manage and schedule processes, handle inter-process communication and synchronize between events within your application.

Even a small, lightweight RTOS offers simple scheduling, inter-process communication and interrupt handling capabilities that make efficient use of the resources in the MPU subsystem.

5.1.2.3. Using Symmetrical vs. Asymmetrical Multiprocessing (SMP vs. AMP) Modes

The Dual Core ARM Cortex-A9 MPCore* in the Cyclone V / Arria V HPS can support both Symmetrical Multi-processing (SMP) and Asymmetrical Multi-processing (AMP) configuration modes.

In SMP mode, a single OS instance controls both cores. The SMP configuration is supported by a wide variety of operating system manufacturers and is the most common and straightforward configuration mode for multiprocessing.

Commercially developed operating systems offer features that take full advantage of the CPU cores resources and use them in an efficient manner resulting in optimum performance and ease of use. For instance, SMP enabled operating systems offer the option of setting processor affinity. This means that each task/thread can be assigned to run on a specific core. This feature allows the software developer to better control the workload distribution for each Cortex-A9 core and making the system more responsive as an alternative to AMP.

GUIDELINE: Familiarize yourself with the performance and optimizations available in commercial operating systems to see if an SMP-enabled OS or RTOS meets your performance and real-time requirements.

In the AMP (Asymmetrical Multi-Processing) configuration, two different operating systems or two instances of a single operating system run on the two cores. The two operating systems have no inherent knowledge of how they share CPU resources. To ensure efficient use of MPU subsystem resources in this environment, you must deal with several complex issues when designing your system.

Caution: Use AMP only if you are familiar with the techniques to manage and schedule processes, handle inter-process communication, synchronize between events, manage secure processes between the two instances of the operating systems.

Note: OS providers do not generally offer support for using their OS in an AMP mode, so a special support agreement is typically needed in this case.

5.1.3. Assembling your Software Development Platform for Linux

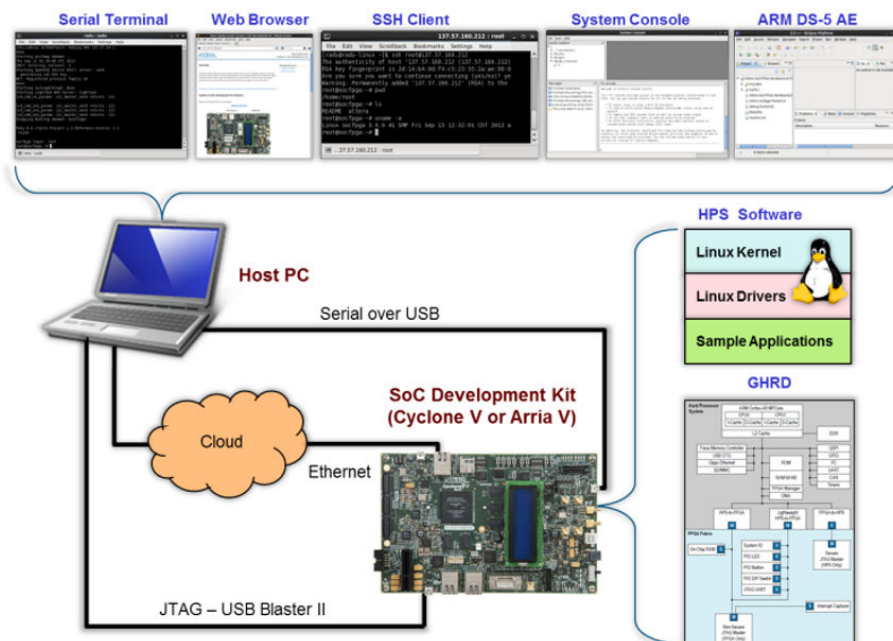
This section presents design guidelines to be used when you have selected Linux as the OS for your end application.

5.1.3.1. Golden System Reference Design (GSRD) for Linux

The Golden System Reference Design (GSRD) for Linux is provided, which consists of the following:

- GHRD (Golden Hardware Reference Design) - A Quartus Prime project
- Reference U-Boot based Bootloader
- Reference Linux BSP
- Sample Linux Applications

Figure 9. GSRD for Linux - Overview



The GSRD for Linux is a well-tested known good design showcasing a system using both HPS and FPGA resources, intended to be used as a baseline project.

GUIDELINE: To successfully build your software development platform, it is recommended that you use the GSRD as a baseline project, then modify it to suit your application needs.

The GSRDs target the Intel SoC Development Boards and are provided both in source and pre-compiled form. They can be obtained from [GSRD User Manuals](#).



GUIDELINE: It is recommended that all new projects use the latest version of GSRD as a baseline.

5.1.3.2. Source Code Management Considerations

The GSRD build process relies on several git trees that are available online, including:

Table 10. Git Tree Link

Git Tree	Link
Intel SoC FPGA Linux Kernel	https://github.com/altera-opensource/linux-socfpga
Intel SoC FPGA Linux designs	https://github.com/altera-opensource/linux-refdesigns
Intel SoC FPGA Angstrom recipes	https://github.com/altera-opensource/angstrom-socfpga

Note: Intel provides Linux enablement, upstreams to mainline and collaborates with the Linux community. Intel provides two kernel versions, the latest stable kernel (N) and latest LTSI kernel (M) and drops support for previous Linux kernel versions (N-1, M-1). At any point in time the (N, N-1, M, M-1) versions are available from the kernel repository. Older kernel versions are removed.

GUIDELINE: Manage your own Git repositories and do not assume the contents of the repositories available on the altera-opensource site remains available. Managing Git repositories can be achieved in many ways, such as using a Git service provider. Some benefits of managing your own Git repositories include build reproducibility, source code management and leveraging the distributed model enabled by Git.

The GSRD uses the Angstrom rootfilesystem, built using Yocto recipes. The recipes pull in various open source package sources, and build them into the rootfilesystem. Because some of these recipes are generic, and do not refer to a specific version, the end result may be different from one build to another.

GUIDELINE: If you rebuild the Yocto rootfilesystem and require repeatability, you must keep a copy of the Yocto downloads folder that was used for the build.

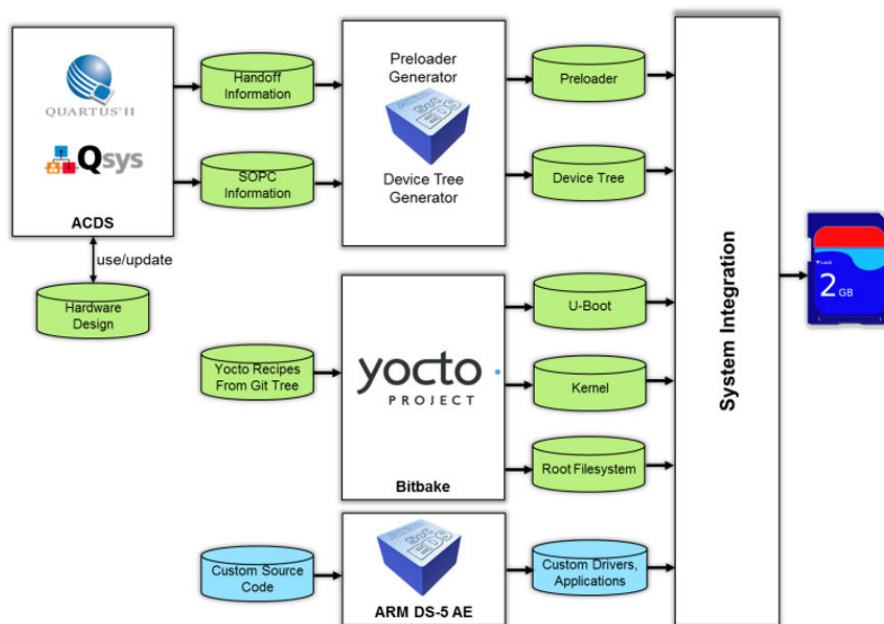
GUIDELINE: If you rebuild the Angstrom rootfilesystem and require repeatability, you must keep a copy of the Yocto downloads folder that was used for the build.

5.1.3.3. GSRD for Linux Development Flow

The figure below presents a high-level view of the development flow for projects based on the GSRD. Refer to the **GSRD User Manuals** link given below for more details.



Figure 10. GSRD for Linux - Development Flow



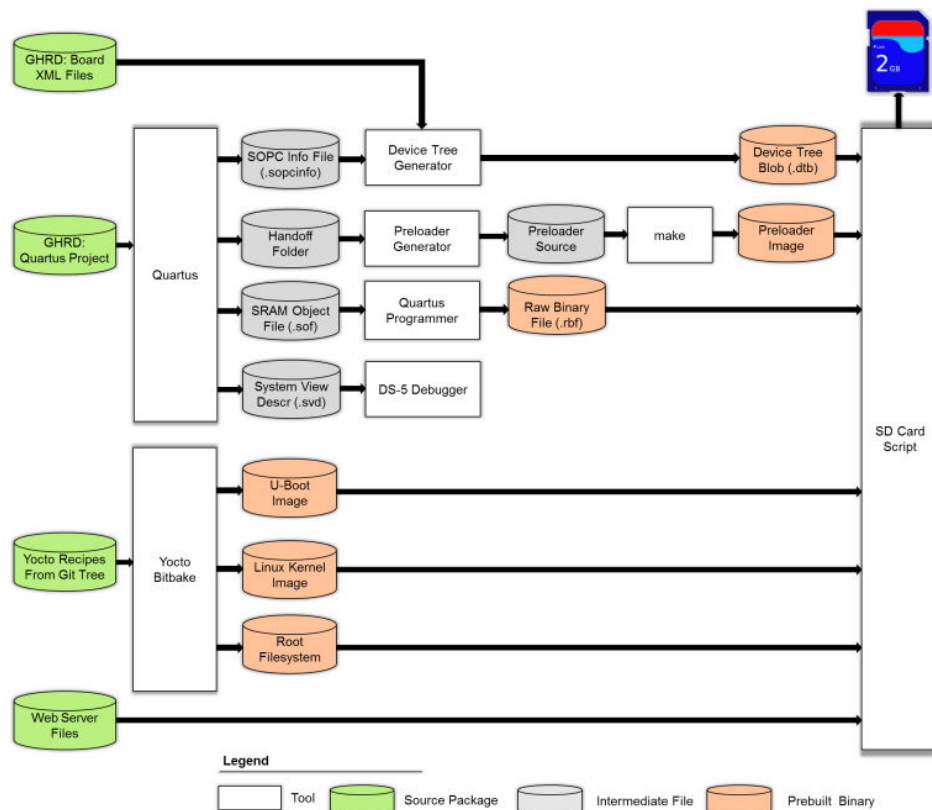
Related Information

[GSRD User Manuals](#)

5.1.3.4. GSRD for Linux Build Flow

The figure below presents a detailed build flow for the GSRD. Refer to the **GSRD User Manuals** link given below for more details.

Figure 11. GSRD for Linux - Build Flow



The above build flow is the one used for the GSRD for Linux but it can be tweaked to match the individual needs of each project. For example:

- Linux kernel could be built separately without using Yocto Bitbake.
- Linux filesystem could be built separately without using Yocto Project.
- Linux Device Tree could be managed without using the Device Tree Generator. For example, it can be manually edited.

Related Information

[GSRD User Manuals](#)

5.1.3.5. Linux Device Tree Design Considerations

The Linux Device Tree is a data structure that describes the underlying hardware to the Linux operating system kernel. By passing this data structure the OS kernel, a single OS binary may be able to support many variations of hardware. This flexibility is particularly important when the hardware includes an FPGA.

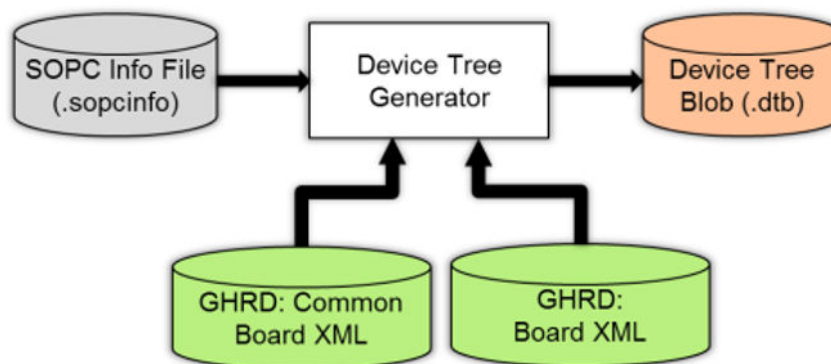
The recommended procedure for managing the Linux Device Tree is:



1. Start with the SoC FPGA reference Device Trees provided in the Linux kernel source code that targets the Intel SoC development kits. They cover the HPS portion of the device but do not cover the FPGA portion which changes on a per-project basis. SD/MMC and QSPI versions are provided with the kernel source code.
2. Edit the Device Tree as necessary to accommodate any board changes as compared to the Intel SoC development kit.
3. Edit the Device Tree as necessary to accommodate the Linux drivers targeting FPGA Soft IP.

Note: The GSRD for Linux uses a different flow than the one recommended above relying on a custom tool called "Linux Device Tree Generator" that is provided as part of SoC EDS.

Figure 12. Device Tree Generation Flow for GSRD for Linux



Refer to the **DeviceTree Generator User Guide** link given below for more details about the Linux Device Tree Generator.

Related Information

[DeviceTree Generator User Guide](#)

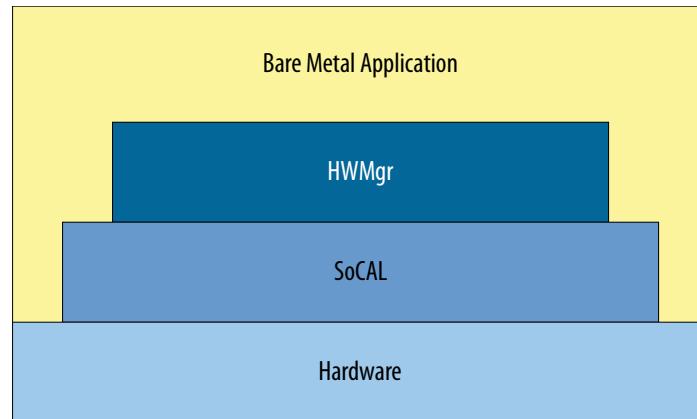
5.1.4. Assembling a Software Development Platform for a Bare-Metal Application

Intel hardware libraries (HWLibs) are low level bare metal software libraries provided with SoC EDS and various components of the HPS. The HWLibs are also typically used by Intel's OS partners to build board support packages for operating systems.

The HWLibs have two components:

- SoC Abstraction Layer (SoCAL): Symbolic register abstraction layer that enables direct access and control of HPS device registers within the address space.
- Hardware Manager (HWMgr): APIs that provide more complex functionality and drivers for higher level use case scenarios.

Figure 13. HWLibs Overview



Note that not all hardware is covered by SoCAL and HWMgr, therefore writing custom code might be necessary depending on the application. Software applications that use HWLibs should have run time provisions to manage the resources of the MPU subsystem, the cache and memory. These provisions are typically what the operating systems provide.

GUIDELINE: It is recommended using HWLibs only if you are familiar with developing a run time provision to manage your application.

GUIDELINE: Use the HWLibs Project Generator to create your customized HWLibs project.

Intel recommends that you create your custom HWLibs project using the HWLibs Project Generator tool, available on RocketBoards.

Related Information

- [Intel® SoC FPGA Embedded Development Suite User Guide](#)
- [Cyclone V Bare Metal Example Using SoC EDS Standard Edition](#)
- [Getting Started with HwLibs Bare Metal Development](#)
- [Design Examples](#)
Additional HWLibs examples

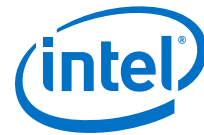
5.1.5. Assembling your Software Development Platform for a Partner OS or RTOS

Partner OS providers offer board support packages and commercial support for the SoC FPGA devices. Typically, partner support includes example getting-started projects and associated documentation.

Note: Please refer to the partner documentation and support services for information on how to assemble the software development platform when targeting a partner OS or RTOS.

5.1.6. Choosing Boot Loader Software

The Cyclone V / Arria V SoC boot flow includes the following stages:



1. Boot ROM
2. Preloader
3. Bootloader
4. Real-time operating system or bare-metal application

Figure 14. Cyclone V / Arria V SoC Boot Flow



The BootROM and Preloader stages are needed for all Cyclone V SoC / Arria V SoC applications. U-boot and Linux are used by the GSRD, but a custom application may implement a different flow, such as using the Preloader to load a bare-metal application directly.

Typically, the main responsibilities of the Preloader are:

- Perform additional HPS initialization
- Bring up SDRAM
- Load the next boot stage from Flash to SDRAM and jump to it

Currently, two different Preloader options are available:

- SPL - part of U-Boot. Provided with SoC EDS under GPL (Open Source) License
- MPL - provided with SoC EDS as an example using the HWLibs (bare-metal libraries). Uses BSD license.

Note:

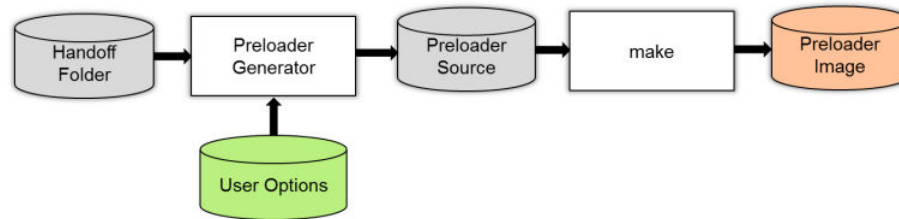
The Preloader requires a special header to be placed at the beginning of the next stage boot image. Also, the header contains a CRC value used to validate the image. The header can be attached to an image by using the mkimage utility that is included with SoC EDS.

The Bootloader has typical responsibilities that are similar with the Preloader, except it does not need to bring up SDRAM. Because the Bootloader is already residing in SDRAM, it is not limited by the size of the OCRAM. Therefore, it can provide a lot of features, such as network stack support.

A typical HPS system had numbers of registers that need to be set for a given configuration of the MPU subsystem, the network-on-chip interconnect component, the SDRAM memory, flash boot source and peripheral interfaces. The settings used for boot or initialization purposes are encapsulated in the following places:

- RBF File(s) - containing register settings for SDRAM also dedicated I/O and FPGA pin configuration.
- U-Boot source code - for rest of the settings

Figure 15. Preloader Build Flow



Note: It is highly recommended that Preloader is generated with bsp-editor. It is also recommended, although not required, to build U-Boot from the same source code.

5.1.7. Selecting Software Tools for Development, Debug and Trace

Note: When using a specific Partner OS or RTOS, consult the OS vendor and the OS documentation for any specific tools that are required. Some OS vendors also provide a full set of tools that are recommended to be used with that OS.

Note: Familiarize yourself with the available tools for development, compilation and debug. A list of supported tools is available at the [Ecosystem](#) tab of the **Intel FPGAs** page.

5.1.7.1. Select Software Build Tools

GUIDELINE: Decide which software development tools to use, and select the tool versions.

Software development tools include compilers, assemblers, linkers, and archivers. The Arm Development Studio 5* (DS-5*) Intel SoC FPGA Edition includes the following software build tools:

- ARMCC Bare-metal Compiler
- Mentor Graphics CodeSourcery Lite GCC-based bare-metal Compiler
- Linux Linaro Compiler

There are also other development tools offerings from third party providers.

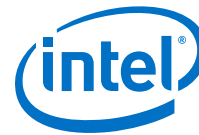
5.1.7.2. Select Software Debug Tools

GUIDELINE: Select software debug tools.

Arm DS-5 Intel SoC FPGA Edition includes a fully featured Eclipse-based debugging environment. There are also other debugging tools offerings from third party providers such as Lauterbach T32.

The debug tools require a JTAG connection to the SoC FPGA device. The connection could be achieved in a couple of ways:

- An embedded USB-Blaster II chip could be available on-board such as on the Cyclone V SoC / Arria V SoC Development Kit.
- External JTAG hardware may be required when using the Lauterbach T32 tools.



5.1.7.3. Select Software Trace Tools

Tracing can be very helpful for profiling performance bottlenecks, debugging crash scenarios and debugging complex cases. Tracing can be performed in two ways:

- **Non-real-time:** by storing trace data in system memory (for example SDRAM) or the embedded trace buffer, then stopping the system, downloading the trace information and analyzing it.
- **Real-time:** by using an external adapter trace data from the trace port. The target board needs to support this scenario.

Typically, the debug tools also offer tracing of the embedded software program execution, but external hardware may be required. For example, the DS-5 provided with the SoC EDS supports both non-real-time and real-time tracing. When used for real-time tracing, an additional external trace unit called "DSTREAM" is required. Lauterbach T32 is a similar example, in that it needs additional external hardware for real-time tracing.

5.2. Flash Device Driver Design Considerations

The SoC FPGAs support the following types of flash devices: QSPI, NAND, SD/MMC/eMMC.

Note:

Please refer to [Supported Flash Devices for Cyclone V and Arria V SoC](#) for a list of supported flash devices. Use an "Intel Tested and Supported" device, to minimize development effort and risk of incompatibility. The next best option is to select a "Known to Work" device. This means that the device is compatible with BootROM and was proven to work with at least one Bootloader - but it may not be the Bootloader you need. It may also not have HWLibs, OS Support or HPS Flash Programmer Support.

5.3. SD Card Low Power Mode Design Considerations

The SD/MMC Controller has a low power mode which is enabled by setting the `cclk_low_power` bit of the **clkena** register to 1. When this mode takes effect, the clock to the card is disabled when the card is idle for at least eight card clock cycles.

During this low power mode, the state of the SD I/O signals are as follows:

- `SD_CLK` = 0
- `SD_CMD` = 1
- `SD_D0 . . 3` = floating

If the end application requires all SD I/O signals to be floating during the low power mode, the following procedure is recommended:

1. When the card is not in use, after the last command:
 - Set the GPIOs associated to the `SD_CMD` and `SD_CLK` pins as inputs by using the **gpio** registers.
 - Change the pin muxing for the `SD_CLK` and `SD_CMD` pins to be GPIO signals by using the **sysmgr.pinmux** registers².
2. When the card is to be used again, before the next command:

- Change back the pin muxing for the SD_CLK and SD_CMD to be SD I/O signals by using the **sysmgr.pinmux** registers.

Note: When the SD/MMC controller is in reset state, the state of the SD I/O signals is as follows:

- SD_CLK = 0
- SD_CMD = floating
- SD_D0 . . 3 = floating

5.4. HPS ECC Design Considerations

ECC is implemented throughout the entire HPS subsystem on all RAMs, including the external HPS EMIF, L2 cache data RAMs and all peripheral RAMs. The controller ECC employs standard Hamming logic to detect and correct single-bit errors and detect double-bit errors. Parity protection is provided for the Cortex-A9 MPCore L1 cache memories and L2 tag RAM. ECC can be selectively enabled on the HPS EMIF and internal HPS RAMs. Diagnostic test modes and error injection capability are available under software control. ECC is disabled by default upon power-up or cold reset.

The generated boot code configures, initializes and enables ECC according to user options selected during BSP generation. Custom firmware and bare metal application code access to the ECC features is facilitated with the Intel-provided HWLibs library, which provides a simple API for programming HPS software features.

For more information, refer to the "Boot Tools User Guide" and "Hardware Library" chapters of the [Intel SoC FPGA Embedded Development Suite User Guide](#).

Related Information

[Intel® SoC FPGA Embedded Development Suite User Guide](#)

5.4.1. General ECC Design Considerations

Each RAM in the HPS subsystem has its own ECC controller with a unique set of features and requirements. However, there are general system integration design issues that you should consider.

5.4.2. System-Level ECC Control, Status and Interrupt Management

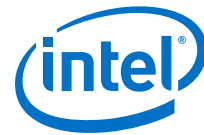
The System Manager contains a set of ECC-related registers for system-level control and status for all the ECC controllers in the HPS subsystem. ECC-related interrupts are also managed through this set of registers.

Related Information

- [System Manager - Cyclone V Hard Processor System Technical Reference Manual](#)
- [System Manager - Arria V Hard Processor System Technical Reference Manual](#)

5.4.3. ECC for L2 Cache Data Memory

The L2 cache memory is ECC protected, while the tag RAMs are parity protected. L2 cache ECC is enabled through a control register in the System Manager.



For details about the L2 cache ECC controller, refer to the following sections in the "Cortex-A9 Microprocessor Unit Subsystem" chapter of the appropriate *Hard Processor System Technical Reference Manual*:

- "Single Event Upset Protection"
- "L2 Cache Controller Address Map for Cyclone V" or "L2 Cache Controller Address Map for Arria V"

GUIDELINE: The L1 and L2 cache must be configured as write-back and write-allocate for any cacheable memory region with ECC enabled.

For BSPs supported by the Intel SoC FPGA EDS, you can configure your BSP for ECC support with the bsp-editor utility.

For bare metal firmware, refer to "L2 Cache Controller Address Map" in the "Cortex-A9 Microprocessor Unit Subsystem" chapter of the appropriate *Hard Processor System Technical Reference Manual*.

GUIDELINE: Cache-coherent accesses through the L3 interconnect using the ACP must perform 64-bit wide, 64-bit aligned write accesses when ECC is enabled in the L2 Cache Controller

Enabling ECC does not affect the performance of the L2 cache, but accesses using the ACP must be 64-bit wide, 64-bit aligned in memory. This includes FPGA masters accessing the ACP over the FPGA-to-HPS Bridge. For a list of possible combinations of bridge width and FPGA master width, alignment and burst size and length, refer to "FPGA-to-HPS Access to ACP" in the "HPS-FPGA Bridges" chapter of the appropriate *Hard Processor System Technical Reference Manual*.

Related Information

- [Cyclone V Hard Processor System Technical Reference Manual](#)
- [Arria V Hard Processor System Technical Reference Manual](#)

5.4.4. ECC for Flash Memory

All peripheral RAMs in the HPS subsystem are ECC protected. The NAND flash controller ECC hardware is not used when a read-modify-write operation is performed from the flash device's page buffer. Software must update the ECC during such read-modify-write operations. For a read-modify-write operation to work with hardware ECC, the entire page must be read into system memory, modified, then written back to flash without relying on the flash device's read-modify-write feature.

The NAND flash controller cannot do ECC validation during a copy-back command. The flash controller copies the ECC data but does not validate it during the copy operation.

5.5. HPS SDRAM Considerations

5.5.1. Using the Preloader To Debug the HPS SDRAM

To debug the HPS EMIF, you can change the settings in the preloader to enable runtime calibration report, debug level information and check the status of HPS SDRAM PLL.

Note: Refer to "Building the Second Stage Bootloader" in the [Intel SoC FPGA Embedded Development Suite User Guide](#) for step-by-step instructions for compiling the preloader.

Related Information

[Intel® SoC FPGA Embedded Development Suite User Guide](#)

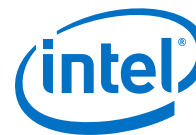
5.5.1.1. Enable Runtime Calibration Report

To enable the runtime calibration report, use your preferred editor to open the <project_folder>\software\spl_bsp\uboot-socfpga\board\altera\socfpga\sdr\sequencer_defines.h file and configure the `RUNTIME_CAL_REPORT` value to 1.

```

101 #define LRDIMM 0
102 #define M10_DQ_WIDTH_8 0
103 #define M10_DQ_WIDTH_16 0
104 #define M10_DQ_WIDTH_24 0
105 #define MARGIN_VARIATION_TEST 0
106 #define MAX_LATENCY_COUNT_WIDTH 5
107 #define MEM_ADDR_WIDTH 13
108 #define MRS_MIRROR_PING_PONG_ATSO 0
109 #define MULTIPLE_AFI_WLAT 0
110 #define NUM_SHADOW_REGS 1
111 #define QDRII 0
112 #define QUARTER_RATE 0
113 #define RDIMM 0
114 #define READ_AFTER_WRITE_CALIBRATION 1
115 #define READ_VALID_FIFO_SIZE 16
116 #define REG_FILE_INIT_SEQ_SIGNATURE 0x5555048c
117 #define RLDGRAM3 0
118 #define RLDGRAMII 0
119 #define RLDGRAMX 0
120 #define RUNTIME_CAL_REPORT 1
121 #define RW_MGR_MEM_ADDRESS_MIRRORING 0
122 #define RW_MGR_MEM_ADDRESS_WIDTH 14
123 #define RW_MGR_MEM_BANK_WIDTH 3
124 #define RW_MGR_MEM_CHIP_SELECT_WIDTH 1
125 #define RW_MGR_MEM_CLK_FN_WIDTH 1

```



5.5.1.2. Change DLEVEL To Get More Debug Information

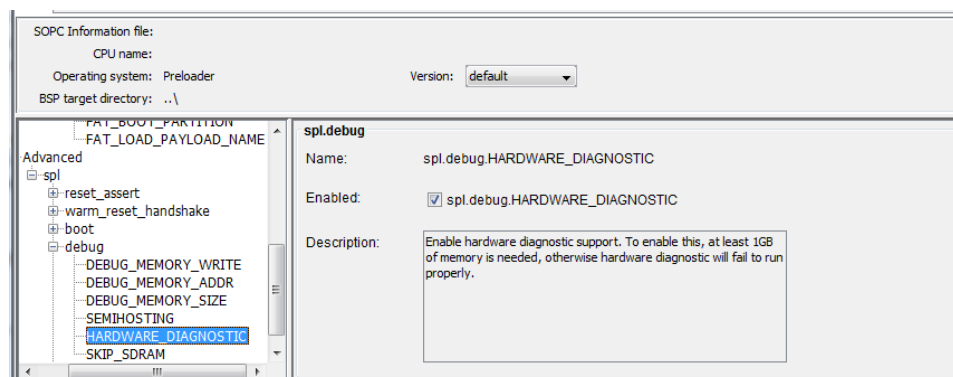
```

C:\SR\PFU_Board\handoff-14.0-533\handoff-14.0-533\hps_isw_handoff\redpepper_sys_hps_0\sequencer.c - Notepad++
File Edit Search View Encoding Language Settings Macro Run Plugins Window ?
sequencer.c sequencer_defines.h
280     snprintf((char*)(debug_printf_output->active_word), PRINTF_READ_BUFFER_SIZE*4, "INFO:" fmt, ## args);
281     wait_printf_queue();
282
283     #define BFM_GBL_SET(field,value)    bfm_gbl.field = value
284     #define BFM_GBL_GET(field)         bfm_gbl.field
285     #define BFM_STAGE(label)           BFM_GBL_SET(stage,label)
286     #define BFM_INC_VFIFO              bfm_gbl.vfifo_idx = (bfm_gbl.vfifo_idx + 1) % VFIFO_SIZE
287     #define COV(label)
288
289     #elif HPS_HW //
290
291     // For HPS running on actual hardware
292
293     #define DLEVEL 2
294     #ifdef HPS_HW_SERIAL_SUPPORT
295     // space around comma is required for varargs macro to remove comma if args is empty
296     #define DPRINT(level, fmt, args...) if (DLEVEL >= (level)) printf("SEQ.C: " fmt "\n", ## args)
297     #define IPRINT(fmt, args...)       printf("SEQ.C: " fmt "\n", ## args)
298     #if RUNTIME_CAL_REPORT
299     #define RPRINT(fmt, args...)        printf("SEQ.C: " fmt "\n", ## args)
300     #endif
301     #else
302     #define DPRINT(level, fmt, args...)
303     #define IPRINT(fmt, args...)
304     #endif

```

5.5.1.3. Enable Example Driver for HPS SDRAM

- Enable with Hardware Diagnostic Option in bsp-editor. Note: Example driver is only available in Intel Quartus Prime version 14.0 and later.
 - PRBS31 Data pattern
 - Write to random address => Read from random address
 - Can select different coverage by changing parameter in spl.c



```

672     sdram_size = sdram_calculate_size();
673 #else
674     sdram_size = PHYS_SDRAM_1_SIZE;
675 #endif
676     printf("SDRAM: %ld MiB\n", (sdram_size >> 20));
677
678 #if (CONFIG_PRELOADER_HARDWARE_DIAGNOSTIC == 1)
679     /* Sanity check ensure correct SDRAM size specified */
680     puts("SDRAM: Ensuring specified SDRAM size is correct ...");
681     if (get_ram_size(0, sdram_size) != sdram_size) {
682         puts("failed\n");
683         hang();
684     }
685     puts("passed\n");
686     /*
687     * A simple sdram memory test
688     * If you want more coverage, change the argument as below
689     * SDRAM_TEST_FAST -> quick test which run around 5s
690     * SDRAM_TEST_NORMAL -> normal test which run around 30s
691     * SDRAM_TEST_LONG -> long test which run in minutes
692     */
693     if (hps_emif_diag_test(SDRAM_TEST_FAST, 0, sdram_size) == 0)
694         hang();
695 #endif /* CONFIG_PRELOADER_HARDWARE_DIAGNOSTIC */

```

5.5.1.4. Change Data Pattern in Example Driver

1. Path for sdram_test.c: <project_folder>\software\spl_bsp\uboot-socfpga\arch\arm\cpu\armv7\socfpga\sdram_test.c
2. Change the test_rand_address function

```

137 /*
138  * Valid arguments for coverage
139  * SDRAM_TEST_FAST -> quick test which run around 5s
140  * SDRAM_TEST_NORMAL -> normal test which run around 30s
141  * SDRAM_TEST_LONG -> long test which run in minutes
142  */
143 int hps_emif_diag_test(int coverage, unsigned int addr_bgn,
144     unsigned int addr_end)
145 {
146     int cnt_max = 1000000, status;
147     unsigned int seed = 0xdeadbeef;
148
149     if (coverage == SDRAM_TEST_NORMAL)
150         cnt_max *= 10;
151     else if (coverage == SDRAM_TEST_LONG)
152         cnt_max *= 1000;
153
154     puts("SDRAM: Running EMIF Diagnostic Test ...");
155     //status = test_rand_address(cnt_max, addr_bgn, addr_end, seed);
156
157     status = test_address_kg(addr_bgn, addr_end);
158
159     if (status)
160         puts("Passed\n");
161     else
162         puts("Failed\n");
163     return status;
164 }

```



5.5.1.5. Example Code to Write and Read from All Addresses

```

79 int test_address_xq( unsigned int addr_bgn, unsigned int addr_end)
80 {
81     int i;
82     int cnt;
83     unsigned int data_temp[3];
84     unsigned int expected_data[3];
85     unsigned int addr, read_data;
86     unsigned int num_address;
87
88     num_address= addr_end/4; //10 BYTE/4
89
90     data_temp[0]=0XFFFFFFF; //initial data for walking 0 pattern
91     data_temp[1]=0X00000001; //initial data for walking 1 pattern
92     data_temp[2]=0XAAAAAAAA; //initial data for A->5 switching
93
94     expected_data[0]=0XFFFFFFF; //initial data for walking 0 pattern
95     expected_data[1]=0X00000001; //initial data for walking 1 pattern
96     expected_data[2]=0XAAAAAAAA; //initial data for A->5 switching
97
98     addr=addr_bgn;
99     printf("\nSTARTED %08X DATA PATTERN (!!! THIS WILL TAKE SEVERAL MINUTES)\n",data_temp[0]);
100    /*write*/
101    for (cnt = 0 ; cnt < num_address ; cnt++ ) {
102        writel(data_temp[0], addr);
103        addr = addr + 4; /* Byte-Addressing */
104        data_temp[0]=ROTATE_RIGHT(data_temp[0]);
105        #ifdef CONFIG_SW_WATCHDOG
106        WATCHDOG_RESET();
107        #endif
108    }
109    printf("\nSTARTED READING\n");
110    addr=addr_bgn;
111    /*read*/
112    for (cnt = 0 ; cnt < num_address ; cnt++ ) {
113        read_data=readl(addr);
114        addr = addr + 4; /* Byte-Addressing */
115        #ifdef CONFIG_SW_WATCHDOG
116        WATCHDOG_RESET();
117        #endif
118    }
119    if (read_data !=expected_data[0]) {
120        printf("!!!!!!FAILED!!!!!! EXPECTED DATA : %08x  READ DATA:%08x\n",expected_data[0],read_data );
121        return 0;
122    }
123    expected_data[0]=ROTATE_RIGHT(expected_data[0]);
124    }
125
126    return i;
127 }

```

Number of logical address = number of bytes /4

writel to write to memory

Byte Addressing

readl to read from memory

5.5.1.6. Read/Write to HPS Register in Preloader

Use the following function:

1. writel to write to HPS register
 - writel(value, address);
2. readl to read from HPS register
 - readl(address);

For example:



1. write logic "0" to GPO

```
writel(0x00000000,0xFF706010);
```

value → address

2. write logic "1" to GPO

```
writel(0x00000001,0xFF706010);
```

3. Read from GPO & store read back value in variable

```
variable =readl(0xFF706010);
```

→ address

gpo

Provides a low-latency, low-performance, and simple way to drive general-purpose signals to the FPGA fabric.

Module Instance	Base Address	Register Address
Egpmwcrpge	0xFF706000	0xFF706010

Offset: 0x10
Access: RW

Bit Fields															
31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
value															
RW: OaD															
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
value															
RW: OaD															

gpo Fields

Bit	Name	Description	Access	Reset
31:0	value	Drives h2f_gpd10 with specified value. When read, returns the current value being driven to the FPGA fabric.	RW	OaD

5.5.1.7. Check HPS PLL Lock Status in Preloader

- Read HPS PLL Status Register in `clock_manager.c` and print out in `spl.c`
 - Define global variable in `clock_manager.c` and "extern variable" in `spl.c`
 - Unable to printout value in `clock_manager.c` as the UART has not been initialized yet

```
.cshrc | sdram_test.c | spl.c | clock_manager.c
44
45 DECLARE_GLOBAL_DATA_PTR;
46
47 extern u32 lock_status_t1;
48 extern u32 lock_status_t2;
49 extern u32 lock_status_t3;
50 extern u32 lock_status_t4;
51

705 //KG Added to check lock status
706 printf("\nKG Testing: Readback from 0xFFD04008 before checking lock status : %8x" , lock_status_t1);
707 printf("\nKG Testing: Readback from 0xFFD04008 after checking lock status : %8x" , lock_status_t2);
708 printf("\nKG Testing: Readback from 0xFFD04008 before clearing lock status : %8x" , lock_status_t3);
709 printf("\nKG Testing: Readback from 0xFFD04008 after clearing lock status : %8x\n\n" , lock_status_t4);
710
```

c)prinout value in spl.c

5.5.2. Access HPS SDRAM via the FPGA-to-SDRAM Interface

The HPS bridges can be enabled from the Preloader (SPL/MPL) or U-Boot and in some cases from Linux.

Note: Preloaders (SPL) and U-Boot generated from SoC EDS 13.1 and later contain extra functionality and built in functions to safely enable the HPS bridges.

To enable the HPS FPGA-to-SDRAM bridge from the Preloader or U-Boot, follow the appropriate steps.

Enabling HPS-to-FPGA Bridges from the Preloader

The Preloader checks the status of the FPGA and automatically enables bridges configured in Platform Designer (Standard) and the BSP if the FPGA is configured. The Preloader supports programming the FPGA before running automatic bridge enable tests and code.

For more information, refer to [GSRD v13.1 - Programming FPGA from HPS](#).



Enabling HPS-to-FPGA Bridges from U-Boot

The `bridge_enable_handoff` command can be run from the U-boot command prompt to enable bridges. This command puts the HPS and SDRAM into a safe state before enabling all bridges after appropriate checks.

For more information, refer to the KDB solution: [How can I enable the FPGA2SDRAM bridge on Cyclone V SoC and Arria V SoC Devices?](#)

A. Support and Documentation

A.1. Support

Technical support for operating system board support packages (BSPs) that are ported to the Intel SoC development kit is provided by the operating system provider.

Support for the Intel SoC FPGA Embedded Development Suite (SoC EDS) and the design tools for FPGA development are provided by Intel. The SoC EDS includes the Arm Development Studio 5 for Intel SoC FPGA Edition Toolkit.

Support of the Intel SoC development kit is provided by Intel.

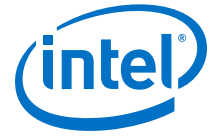
Technical Support for other boards is provided by the respective board provider or distributor.

Item	Supported Through
Commercial operating system and tools	Operating System and Tools Vendor
HardwareLibs (Bare Metal)	Intel
Intel SoC FPGA EDS	Intel
Arm DS-5 for Intel SoC FPGA Edition	Intel
FPGA design tools	Intel
Open Source and Linux	RocketBoards.org
UBoot	RocketBoards.org

For additional information, please refer to these links given below.

Related Information

- [Ecosystem tab of the Intel FPGAs page](#)
- [Support](#)
Support for Intel FPGA products
- [End Market Related Designs](#)
Reference designs and design examples for Intel FPGA products
- [Intel FPGA Design Solutions Network](#)
- [Intel Support Center](#)
- [Design Examples for Intel FPGA products](#)
- [Development Kits, Daughter Cards & Programming Hardware Support](#)
- [Intel FPGA Wiki](#)



A.2. Software Documentation

Driven by the feature-updating nature of today's open source embedded software, most of our software documentation is also hosted on community web.

For more information, please refer to the links given below.

Related Information

- [RocketBoards.org Documentation Portal](#)
- [Altera Opensource](#)
RocketBoards.org repository of Linux-related source code
- [RocketBoards.org Boards](#)
- [RocketBoards.org Projects](#)
- [Intel SoC FPGA Embedded Development Suite User Guide](#)
- [Download SoC EDS](#)
Getting Started tab of the **Intel SoC FPGA Embedded Development Suite** page

B. Additional Information

B.1. Cyclone V and Arria V SoC Device Guidelines Revision History

Document Version	Description
2020.07.27	<p>The following sections were updated:</p> <ul style="list-style-type: none"> • <i>Embedded Software Design Guidelines for SoC FPGAs</i> section: <ul style="list-style-type: none"> — Added <i>Source Code Management Considerations</i> — Added <i>SD Card Low Power Mode Design Considerations</i> • <i>Design Guidelines for HPS portion of SoC FPGAs</i> section: <ul style="list-style-type: none"> — Avoid ACP Dependency Lookup
2019.07.16	Added <i>HPS Address Mirroring</i> under the <i>Design Guidelines for HPS portion of SoC FPGAs</i> section to describe HPS SDRAM mirror rank support in SoC.
2018.06.18	Updated the <i>Early Power Estimation</i> section to include information for CVSoC L.
2017.12.22	<ul style="list-style-type: none"> • Update product names • "Background: Comparison between SoC FPGA and SoC FPGA HPS Subsystem" chapter: <ul style="list-style-type: none"> — Remove overview and block diagram of L3 interconnect — Remove SDRAM controller block diagram — Clarify description of FPGA-to-SDRAM access — Remove detailed descriptions of HPS-FPGA system topologies — Guidelines added: <ul style="list-style-type: none"> • Use the lightweight HPS-to-FPGA bridge to connect IP that needs to be controlled by the HPS. • Do not use the lightweight HPS-to-FPGA bridge for FPGA memory. Instead use the HPS-to-FPGA bridge for memory. • Use the HPS-to-FPGA bridge to connect memory hosted by the FPGA to the HPS.. • If memory connected to the HPS-to-FPGA bridge is used for HPS boot, ensure that its slave address is set to 0x0 in Platform Designer (Standard). • Use the FPGA-to-HPS bridge for cacheable accesses to the HPS from masters in the FPGA. • Use the FPGA-to-HPS bridge to access cache-coherent memory, peripherals, or on-chip RAM in the HPS from masters in the FPGA. • Use the FPGA-to-SDRAM ports for non-cacheable access to the HPS SDRAM from masters in the FPGA.

continued...



Document Version	Description
	<ul style="list-style-type: none"> "Design Guidelines for HPS portion of SoC FPGAs" chapter: <ul style="list-style-type: none"> Recommend the Cyclone V HPS-FPGA Bridge Reference Design Example instead of the Cyclone V Datamover Design Example GPIO not recommended for high-speed serial interfaces Guidelines added: <ul style="list-style-type: none"> Use the Golden System Reference Design (GSRD) as a starting point for a loosely coupled system. Use the Cyclone V HPS-to-FPGA Bridge Design Example reference design to determine your optimum burst length and data-width for accesses between FPGA logic and HPS. Guidelines removed: <ul style="list-style-type: none"> Intel recommends that you use the Golden System Reference Design (GSRD) as a starting point for a loosely coupled system. Intel recommends that you use the Cyclone V HPS-FPGA Bridge Reference Design Example to optimize your hardware design and software solutions to achieve high performance real time application with HPS ARM processor. "Board Design Guidelines for SoC FPGAs" chapter: <ul style="list-style-type: none"> RGMII supported by HPS dedicated I/O Guidelines added: <ul style="list-style-type: none"> If your design uses QSPI flash with 4-byte addressing, design the board to ensure that the QSPI flash is reset or power-cycled whenever the HPS is reset. If your SPI peripheral requires the SPI master slave select to stay low during the entire transaction period, consider using GPIO as slave select, or configure the SPI master to assert slave select during the transaction. Ensure that the SD/MMC card is reset whenever the HPS is reset. For bare-metal applications, avoid using a QSPI flash device larger than 16 MB With a QSPI device larger than 16 MB, use QSPI extended 4-byte addressing commands if supported by the device "Embedded Software Design Guidelines for SoC FPGAs" chapter: <ul style="list-style-type: none"> Reference DTB for NAND-based boot no longer supplied Clarify NAND flash interface type required for booting support
2017.02.20	Initial Release